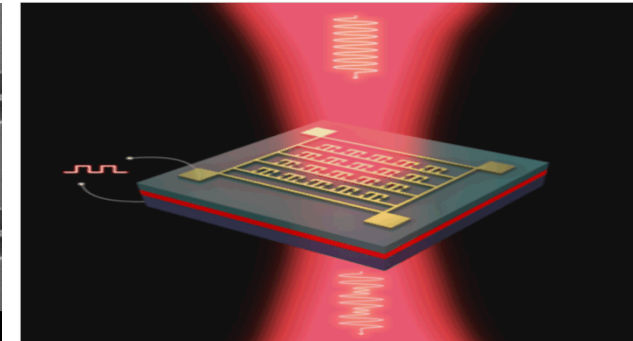
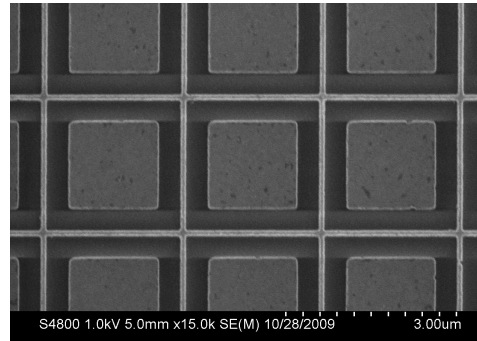
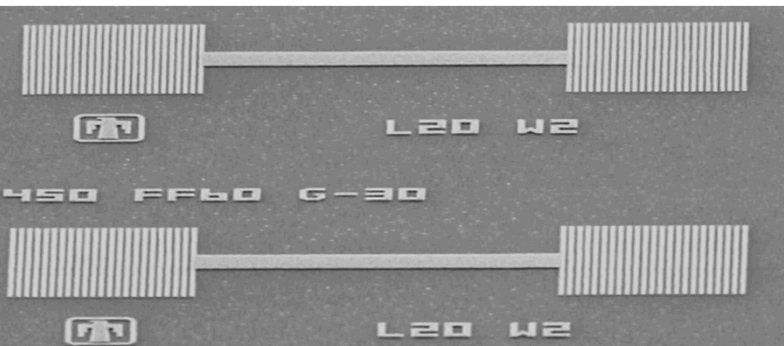


Exceptional service in the national interest



Surface Wave Enabled Infrared Detectors (and other photonic and plasmonic devices)

David W. Peters
dwpeter@sandia.gov

Sandia National Laboratories



1950s

NW production
engineering &
manufacturing
engineering

1960s

Development
engineering
Vietnam conflict

1970s

Multiprogram
laboratory
Energy crisis

1980s

Missile defense
work
Cold War

1990s

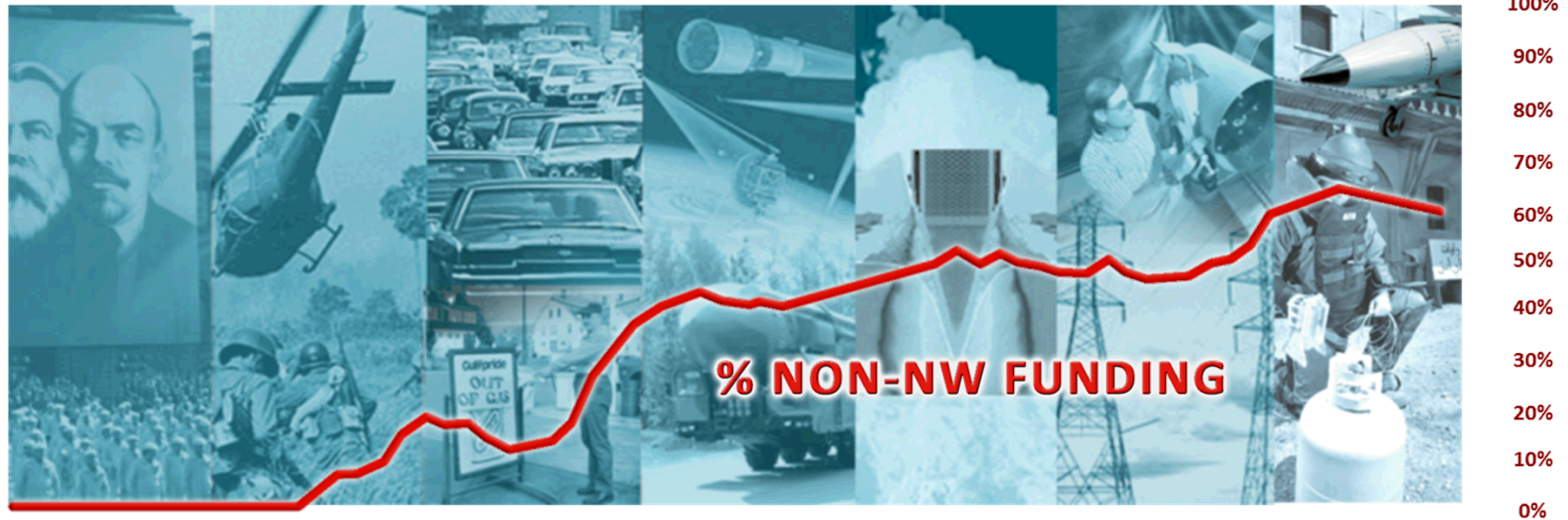
Post-Cold War
transition
Stockpile
stewardship

2000s

Expanded national
security role
post 9/11

2010s

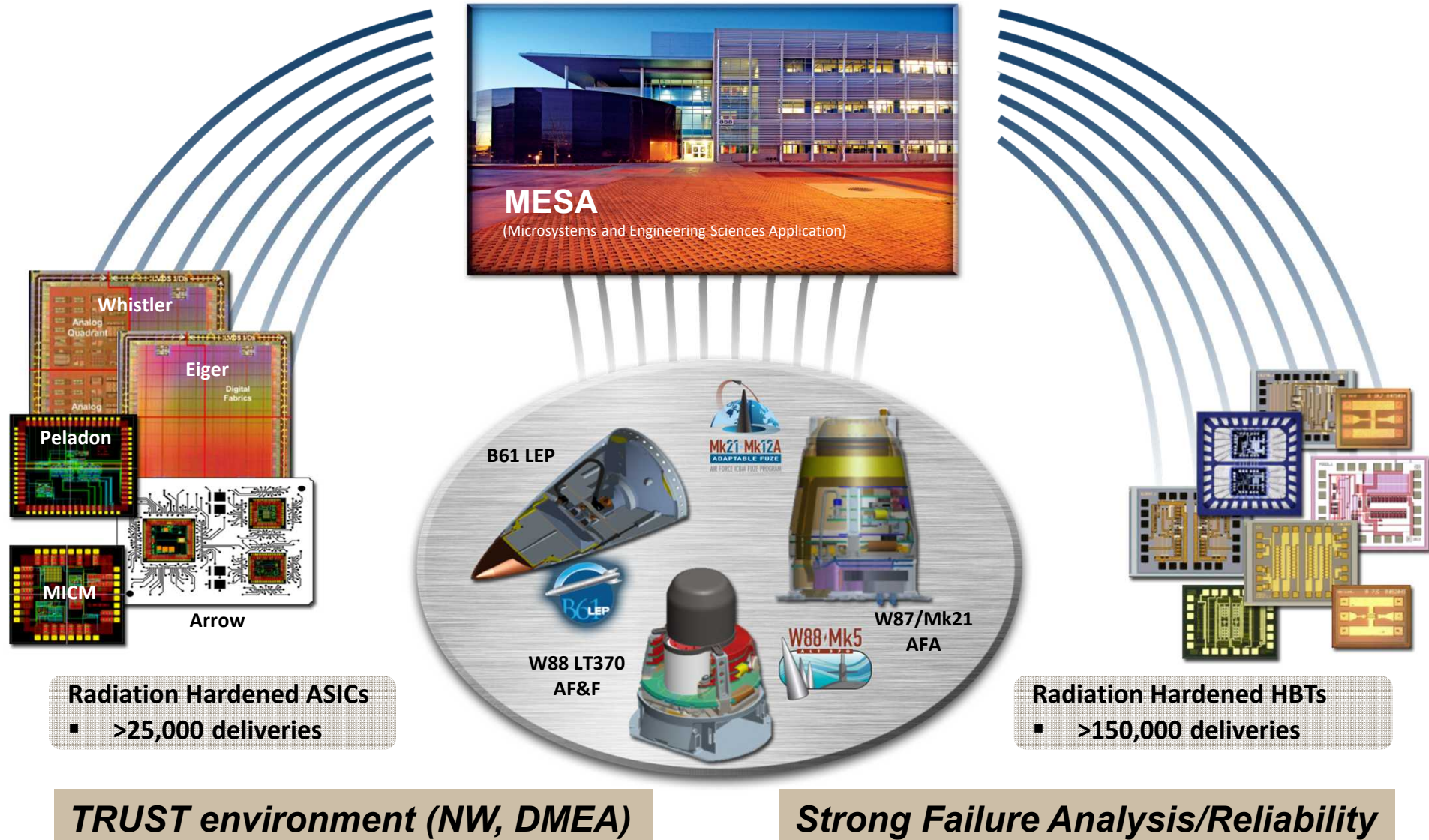
LEPs
New START
Evolving national
security challenges



- DOE FFRDC: Initially Z-division of Manhattan Project (Non-nuclear components, weaponization of NEP)
- **National security tech transition:** Gov't agencies (and/or academia) → SNL → Industry
- Our Big 3: Non-compete with Industry, Fairness of Opportunity, No Organizational Conflict of Interest
- Managed by LMC (but see OCI above)
- CRADAs with many defense contractors, many STTRs & SBIRs, BAA response teaming
- Experience handling sensitive & proprietary information
- DOE supports our "Strategic Partnership Projects" (with industry & other gov't agencies (OGAs))

Microsystems and Engineering Sciences Applications (MESA) Sandia National Laboratories

Manufactures strategic radiation-hardened trusted components for nuclear weapons



MESA: 400,000 ft² Complex with >650 Employees in a Secure Facility

- Trusted Digital, Analog, Mixed Signal & RF Integrated Circuits Design & Fabrication
- Custom IC Design
 - Secure microcontrollers
 - Sensor Readout ICs
 - Analog/Digital/RF
 - IBM Trusted Foundry
 - Tamper Resistant
- Micromachining
- RAD Effects and Assurance
- Failure Analysis, Reliability Physics
- Test & Validation
- 3-D Integration Features

- Advanced Computation
- Modeling & Simulation
- COTS Qualification
- Advanced Packaging
- Custom Electronic Components
- System Design & Test

Silicon Fabrication

Si

Compound Semiconductor Fabrication

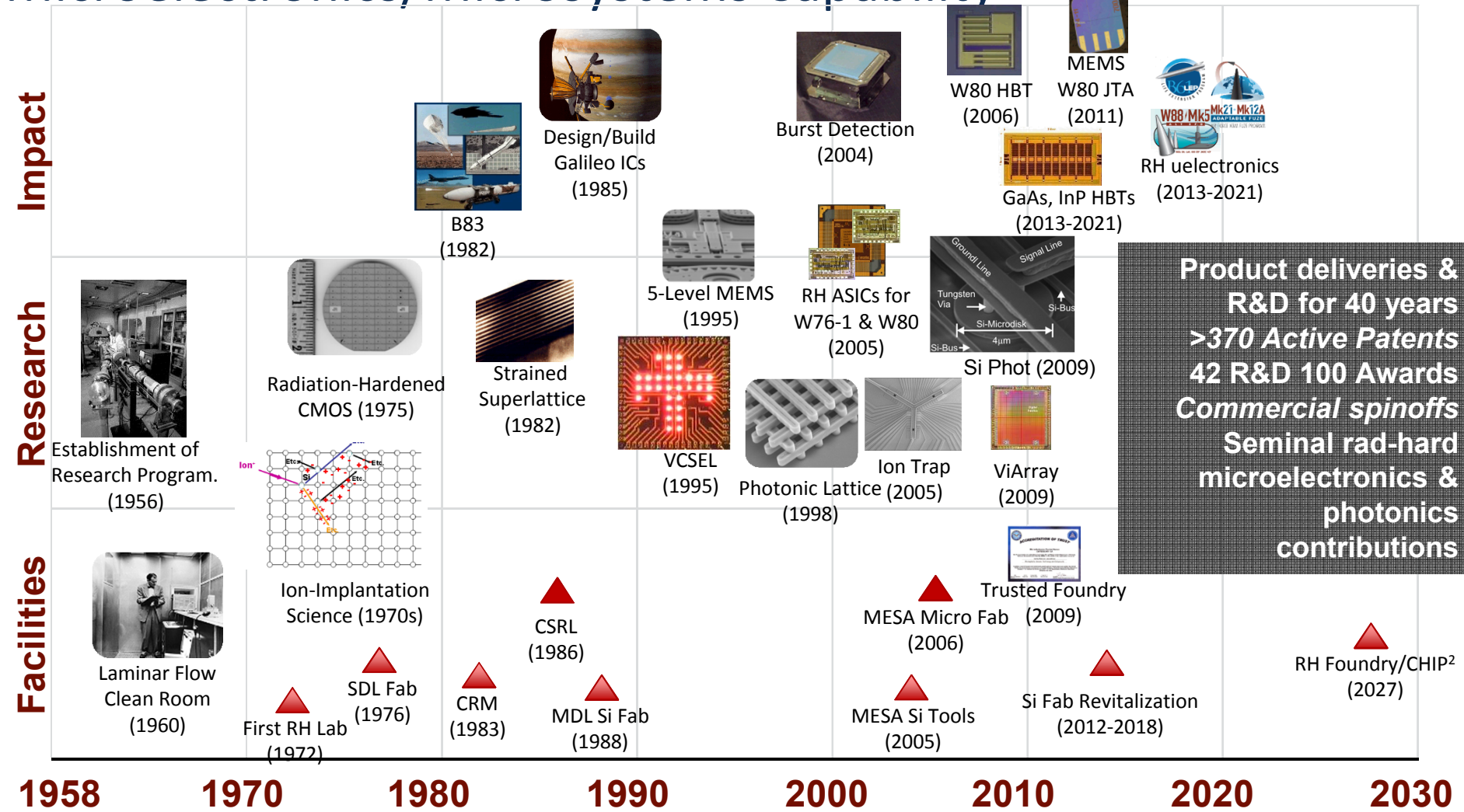
III-V

Materials Research

- Compound Semiconductor Epitaxial Growth (UV-THz)
- Photonics: Si & III-V
- MEMS, VCSELs, Plasmonics
- Specialized Sensors, FPAs
- Materials Science, Graphene
- Nanotechnology, Chem/Bio
- Heterogeneous-Technology Integration & Processing
- III-V Semiconductor Devices
 - Neutron-Immune HBT
 - Rad-hard Optical Links
 - Solid-State RF Devices
 - GaN Power Electronics

MESA is an FFRDC-based development and production facility for any microsystem component or technology that cannot or should not be obtained commercially.

R&D enables and sustains Sandia's Radiation-Hardened Microelectronics/Microsystems Capability



Product deliveries & R&D for 40 years
>370 Active Patents
42 R&D 100 Awards
Commercial spinoffs
Seminal rad-hard microelectronics & photonics contributions

MISSION: Invent and mature integrated circuit and microsystems technologies that provide differentiation and impact for NW and other national security missions.

Trusted Advanced Pathfinder Products: Si Photonics

2014

balanced homodyne resonant wavelength stabilization > 55C

2013

Si Photonics MPW (CIAN NSF ERC)

2012

24 GHz Si TW MZM

2011

45 GHz Ge Detector

2010

3 fJ/bit resonator modulator, 1V-cm MZM

2009

wavelength tunable rings over 35 nm

2008

2.4 ns Wavelength selective switch

2007

MicroDisk resonator infrared detector

2005

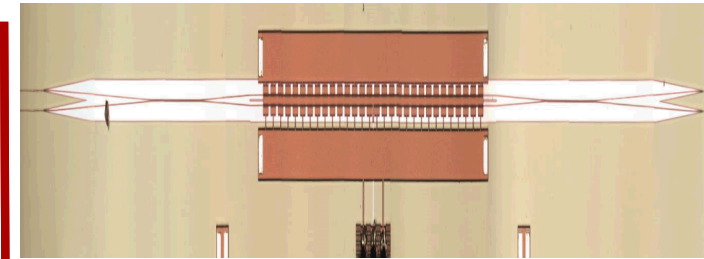
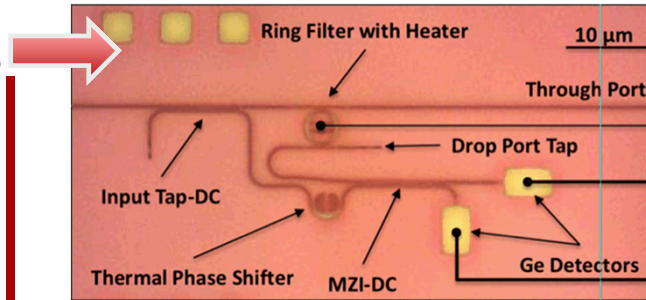
Si₃N₄ low-loss waveguides

2000

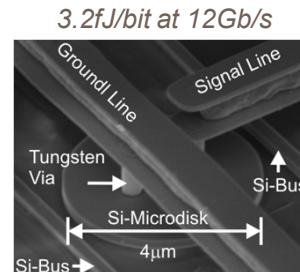
SiON / SiO₂ (Clarendon Photonics)

1990s

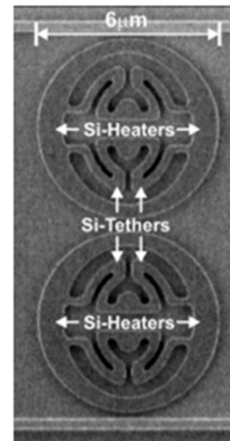
Si PhC & Optical MEMS



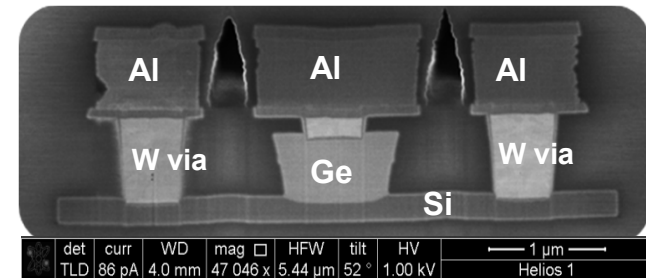
24 GHz 0.7V-cm Travelling Wave MZI Modulator



Resonant Optical Modulator/Filter

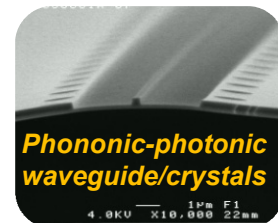


Tunable Resonant Filter

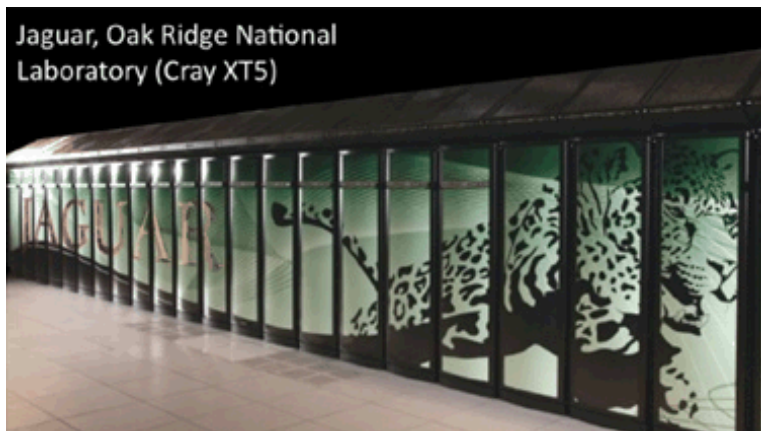


45 GHz High-speed Ge Detector on Si

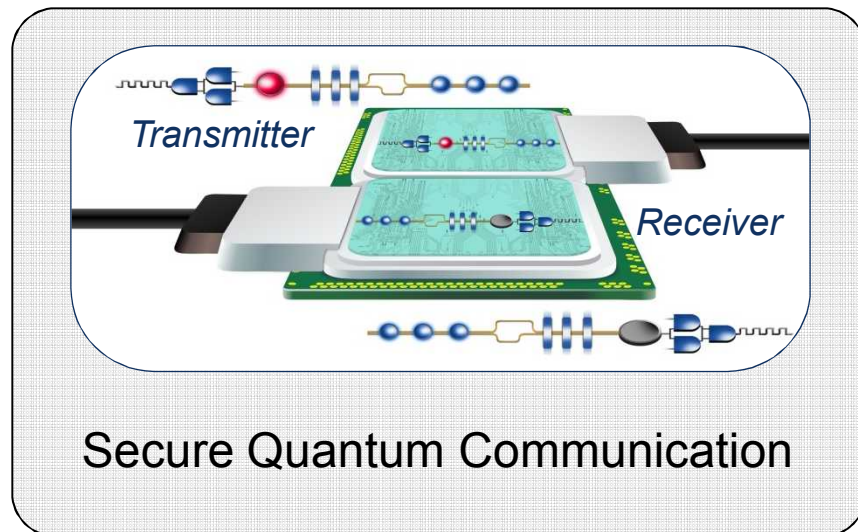
MEMS process for additional capability



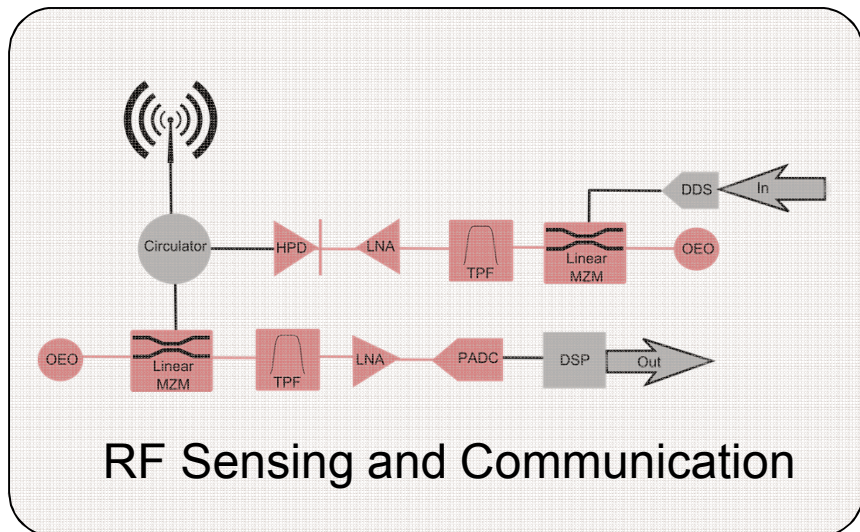
Photonics Enabled System Applications



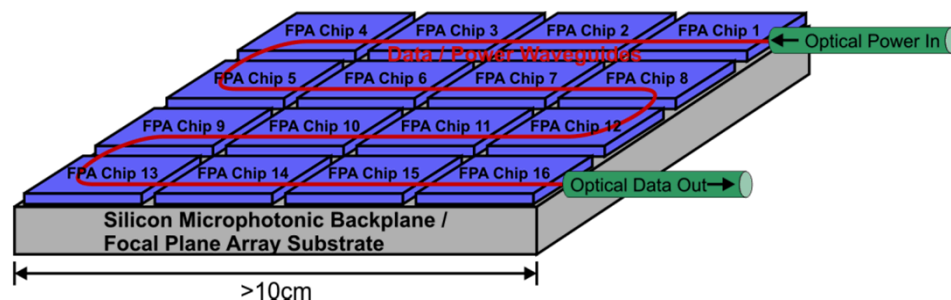
High Performance Computing



Secure Quantum Communication

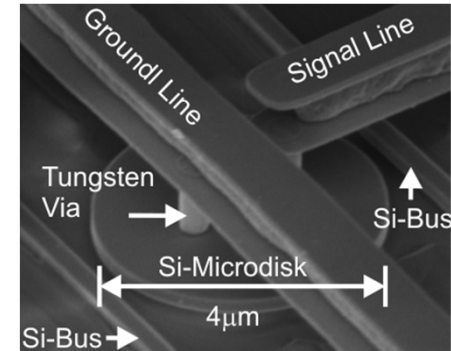
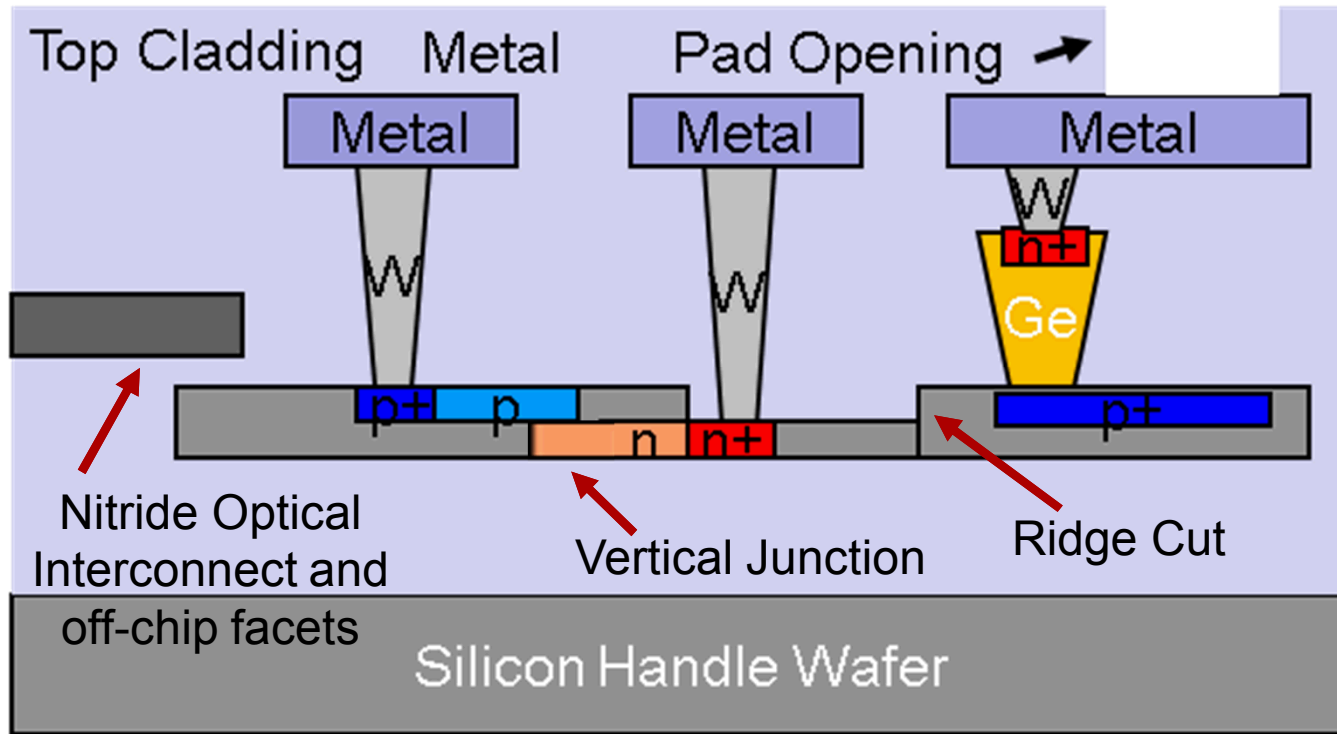


RF Sensing and Communication

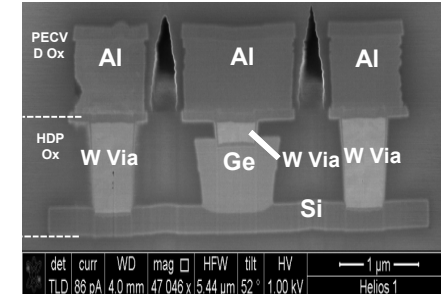


Focal Plane Array Communications

SNL Silicon Photonics Process



*Optical modulator
12.5GHz, 3fJ/bit*



*Ge photo detector with
45GHz BW, 3nA dark current*

- CMOS compatible
- Passive and active photonics devices
 - Silicon and silicon nitride waveguides, couplers, splitters, gratings, filters, modulators, Germanium detectors, switches, etc.

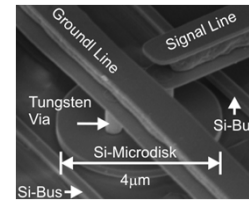
Si Photonics for Detector Communication

Silicon Photonics Capabilities:

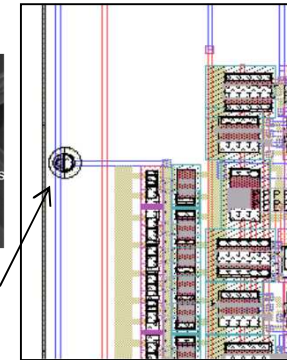
- Modulator energy < 1 fJ/bit
 - 10,000 X lower than commercial optical transceivers in radiation environment
- Low voltage CMOS drive $< 0.5V$
- Bit rates > 10 Gb/s, future 25 Gb/s
- DWDM: > 1 Tb/s per fiber connection
- Scalable beyond Petabits per sec total

Si Photonics-CMOS Integration

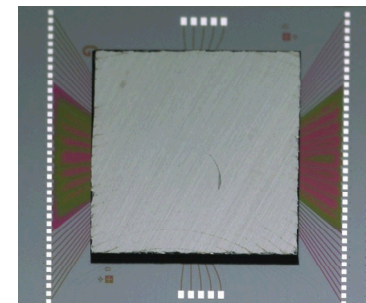
Monolithic *Flip-chip bonding*



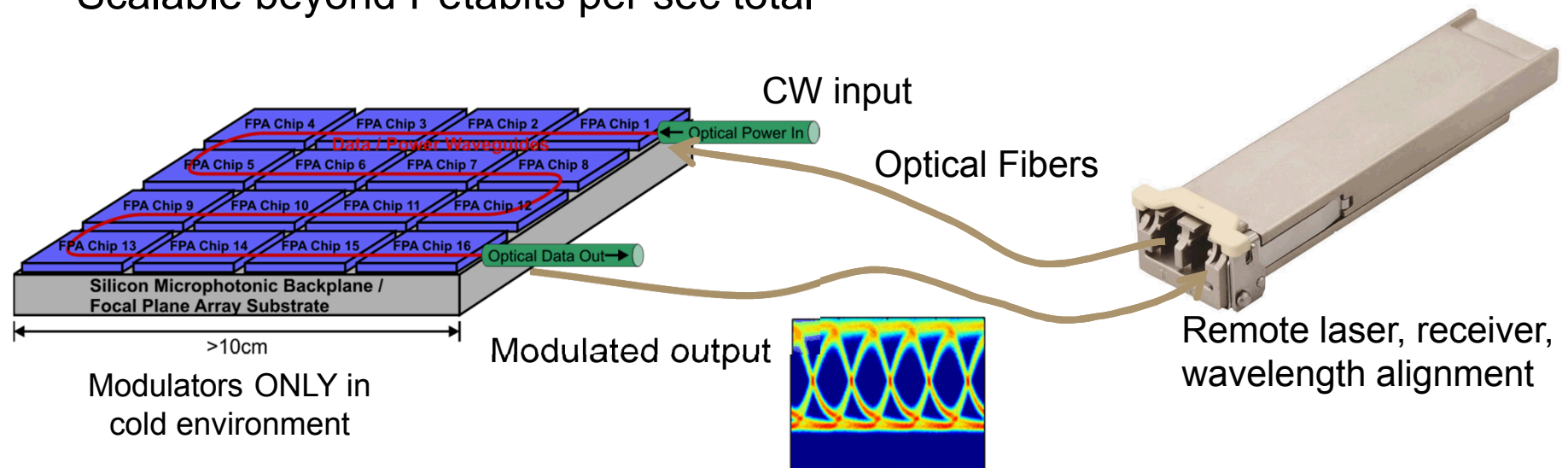
Resonant modulator



CMOS-7



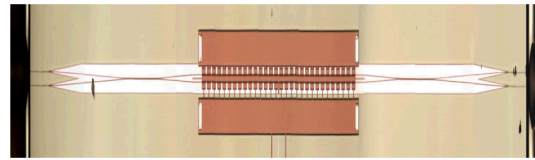
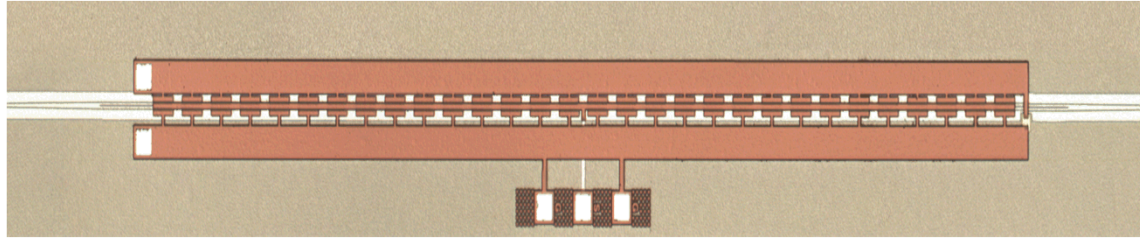
Trusted CMOS



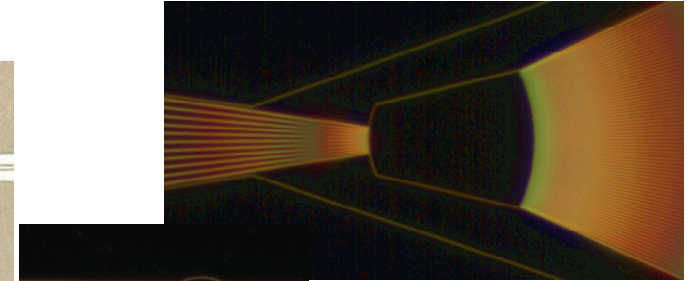
SNL RF Si Photonics Technologies

Silicon Photonics

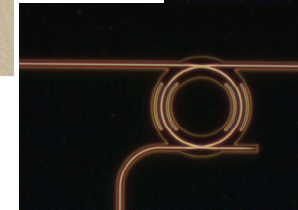
Optical modulation and spectrum analysis up to 100GHz



*Mach-Zehnder Modulator with
Traveling-Wave Electrodes
20GHz, $V_{pi} \times L = 0.8Vcm$*



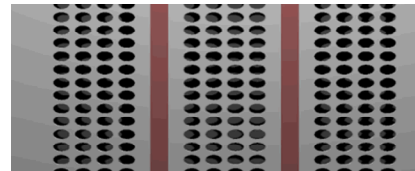
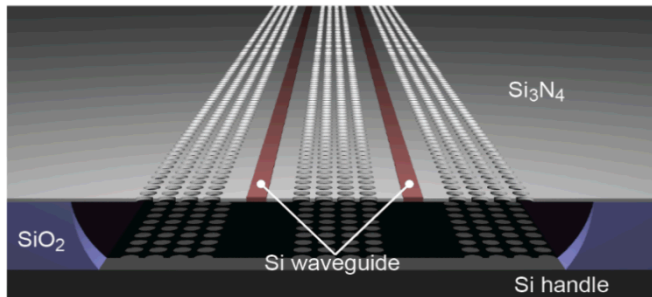
*Array Waveguide
Grating Coupler*



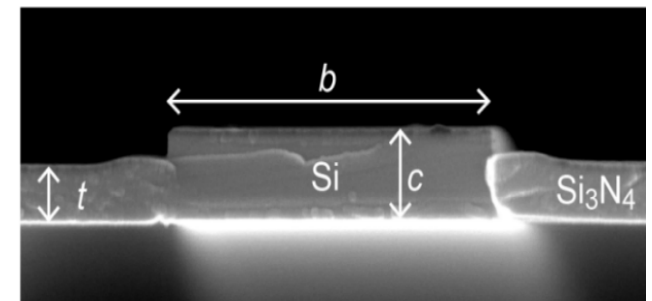
*Micro-ring Tunable
Filter (MHz – GHz)*

Silicon / SiN Nano-Optomechanics

Photon-phonon transduction for signal processing with up to 20GHz BW



*Suspended Si waveguides
with phononic crystals*

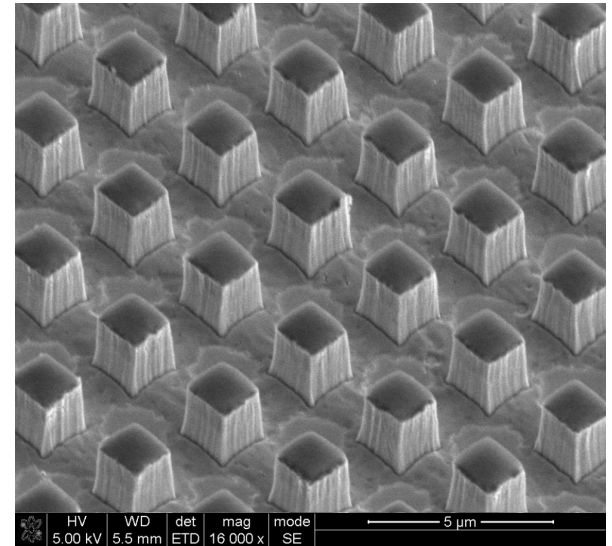


- New paradigm for RF signal processing (ex. filtering) in optical domain to reduce size, weight, and power, and improve performance

Dielectric and Metallic Metamaterials

First ever all dielectric infrared metamaterial:

- best route to low loss metamaterials
- demonstrated negative permeability and permittivity at IR wavelengths
- new resonator designs for negative index behavior

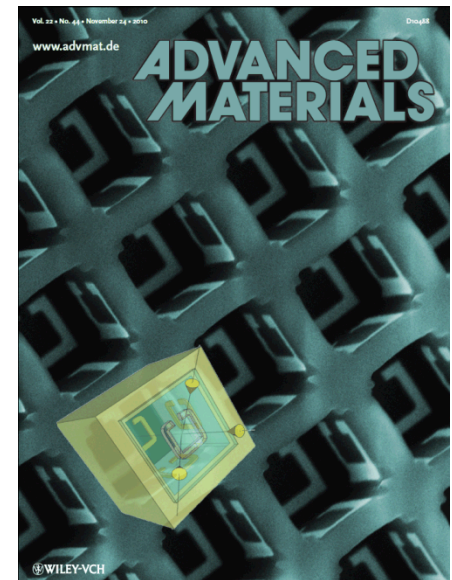
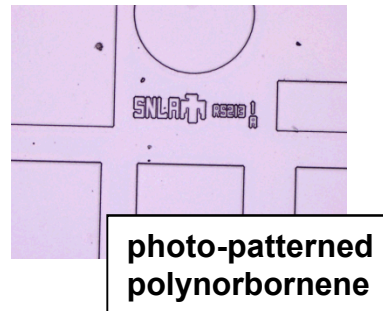


Membrane Projection Lithography:

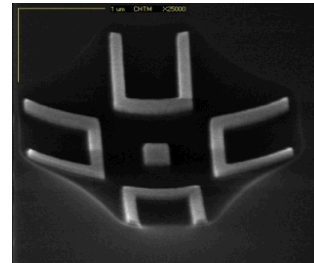
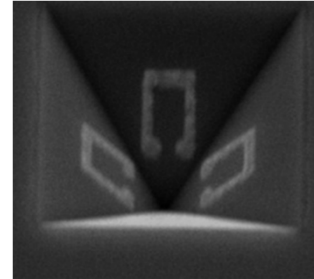
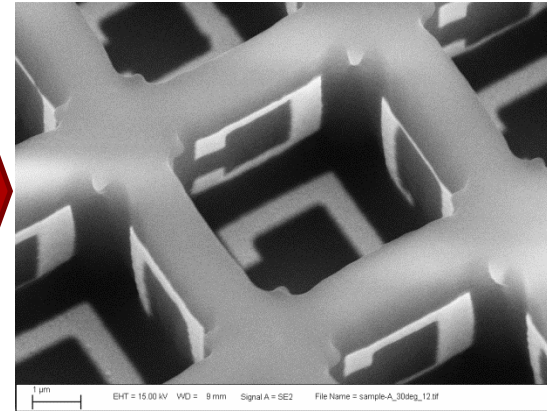
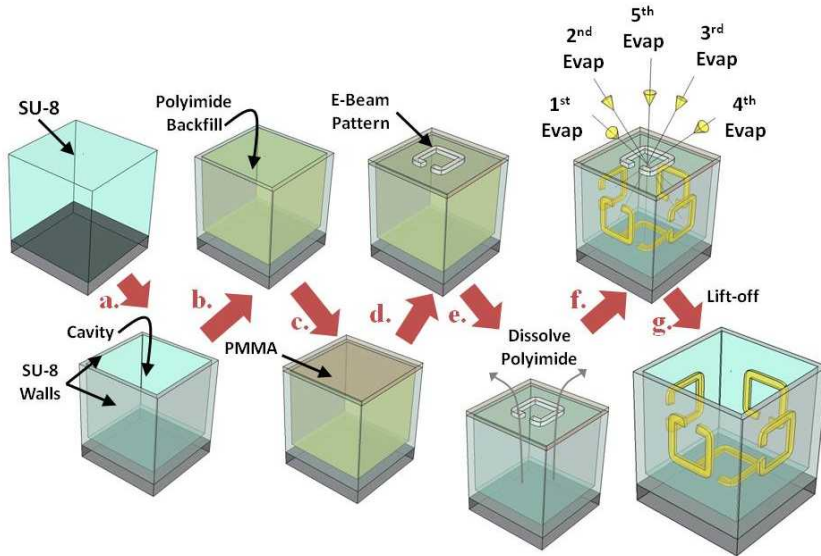
- a new 3D fabrication tool
- metallic resonators with out-of-plane currents
- isotropic metamaterials.

Polynorbornene:

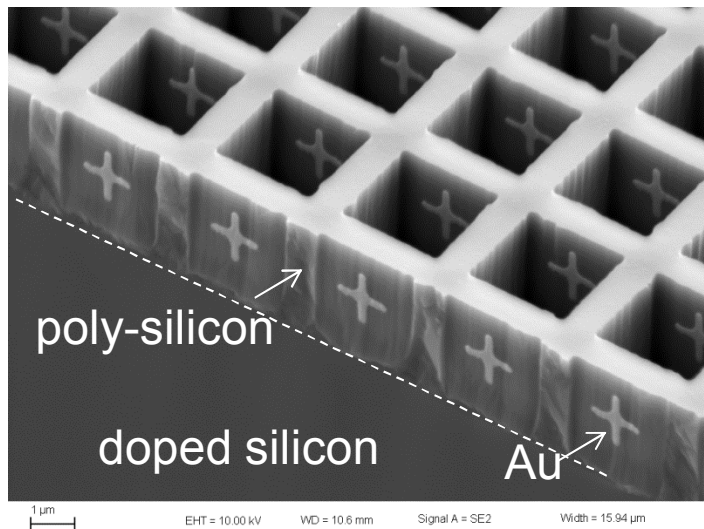
- SU8 of the IR
- low IR loss polymer
- photo cross-linkable
- wide ranging applications



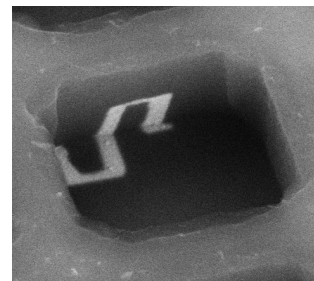
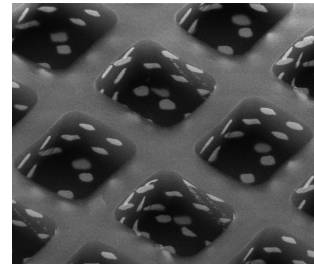
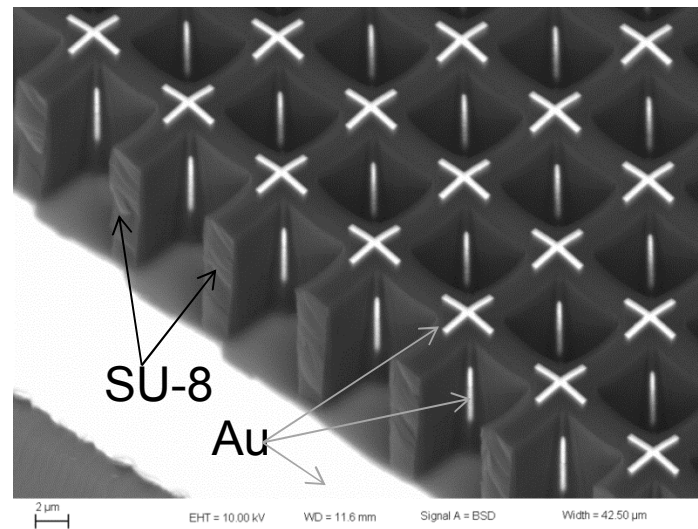
Membrane Projection Lithography



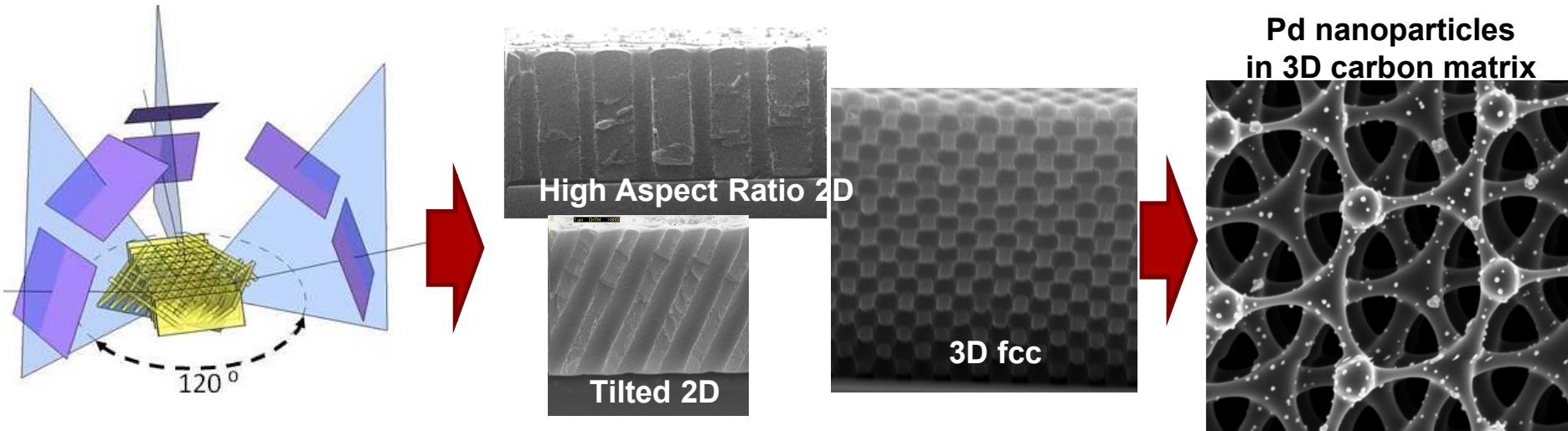
CMOS Compatible Inorganic Material Set



Polymer-Based Material Set



3D Pyrolyzed Carbon

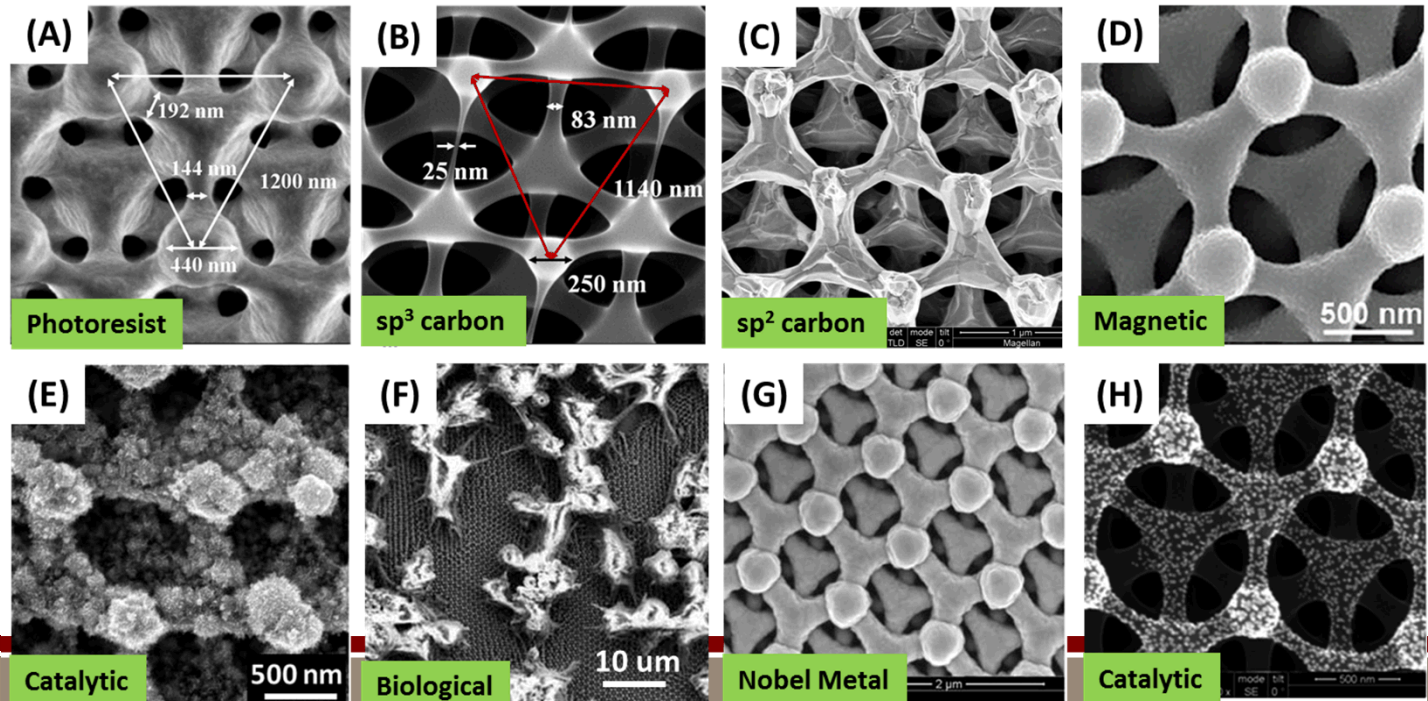


Interferometric Lithography

Resist Patterns

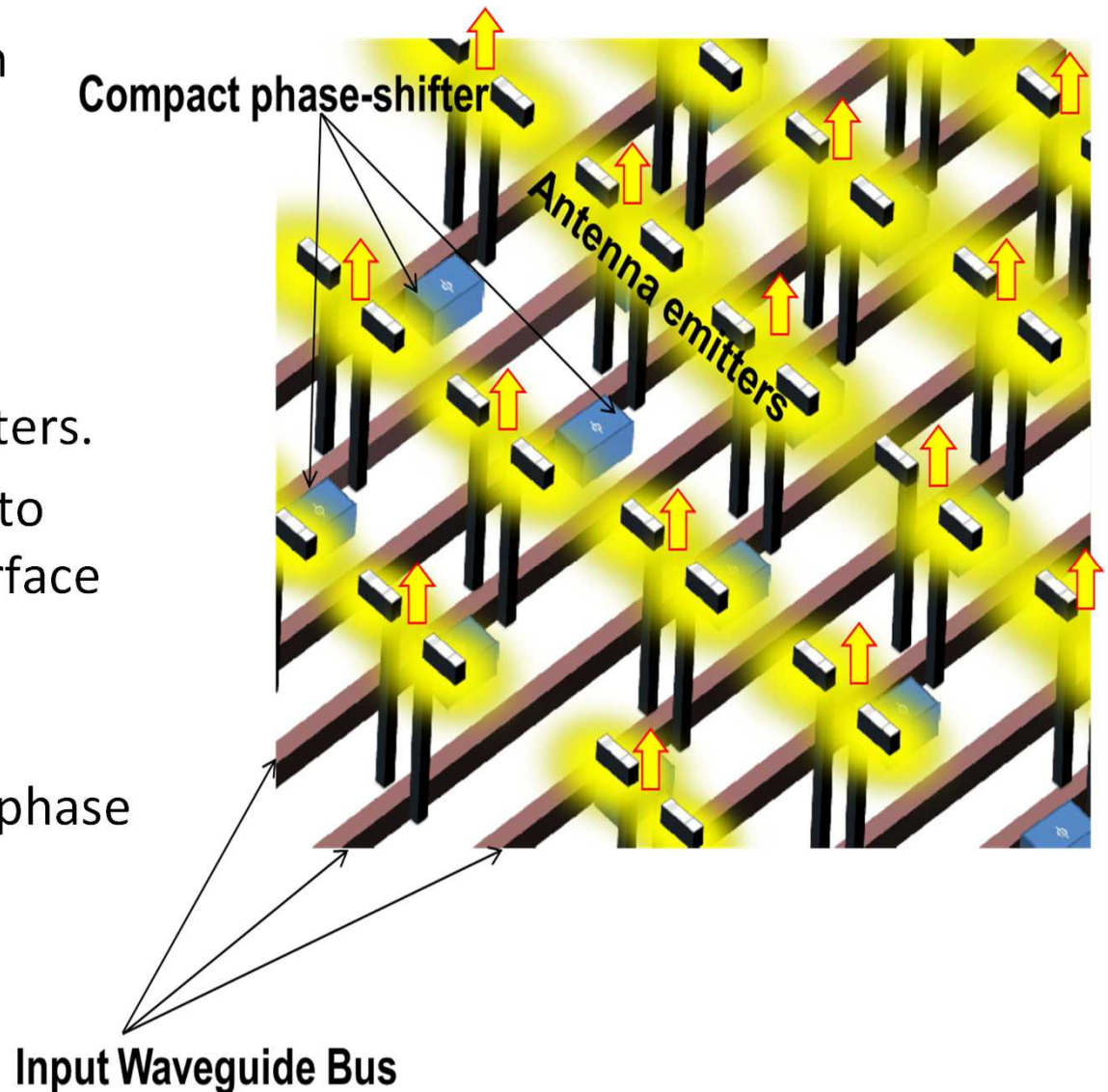
Carbon Scaffold

Scaffolds readily modified using a variety of methods and materials



Free-Space Infrared Communication

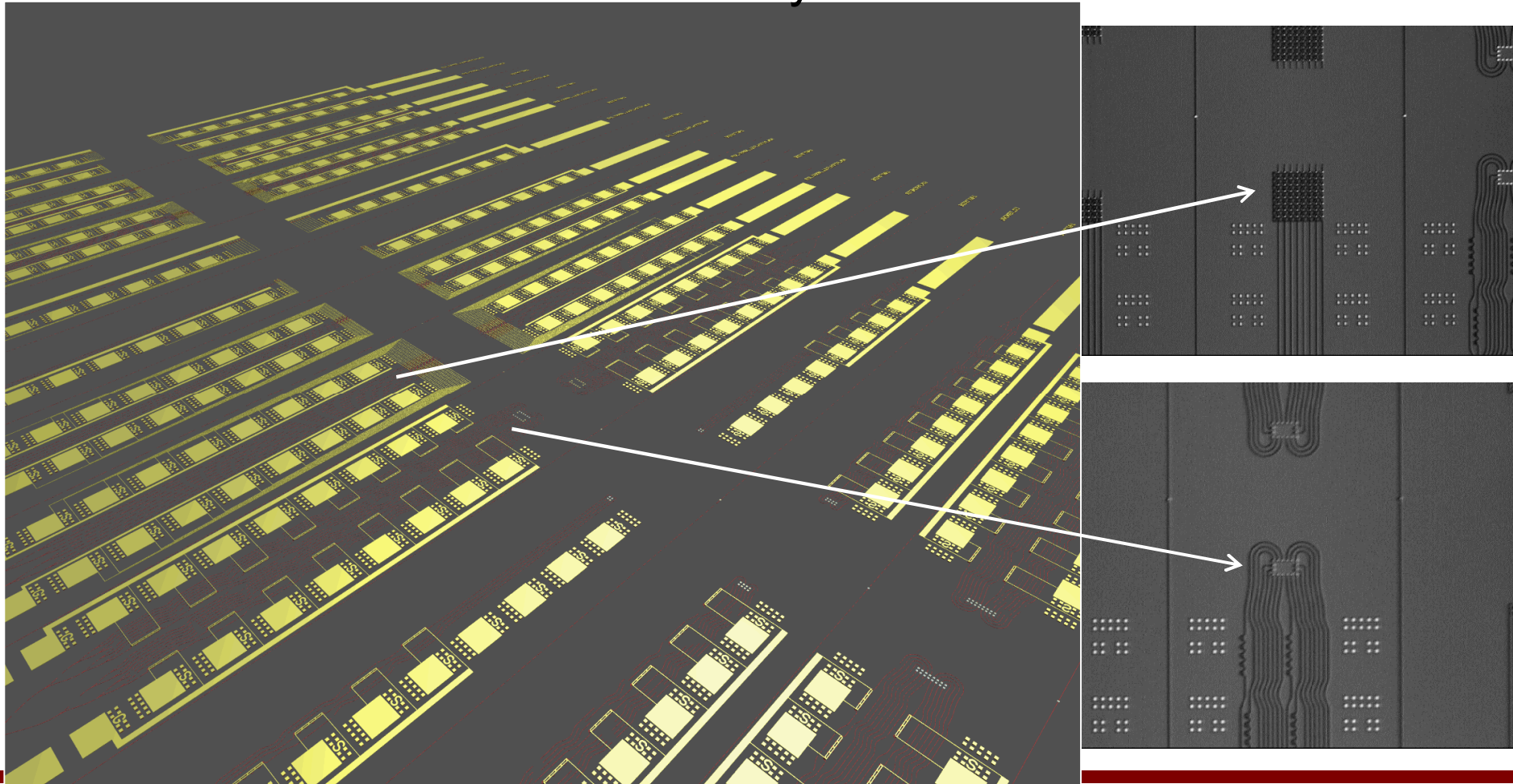
- Use Si Photonics Platform
 - Low loss dielectric waveguides. (light distribution)
 - Integrate compact waveguide phase shifters.
 - Use metallic antenna to radiate efficiently (surface normally)
- Place in periodic array
 - Electronically control phase of each antenna



Phased Array Test-Chip

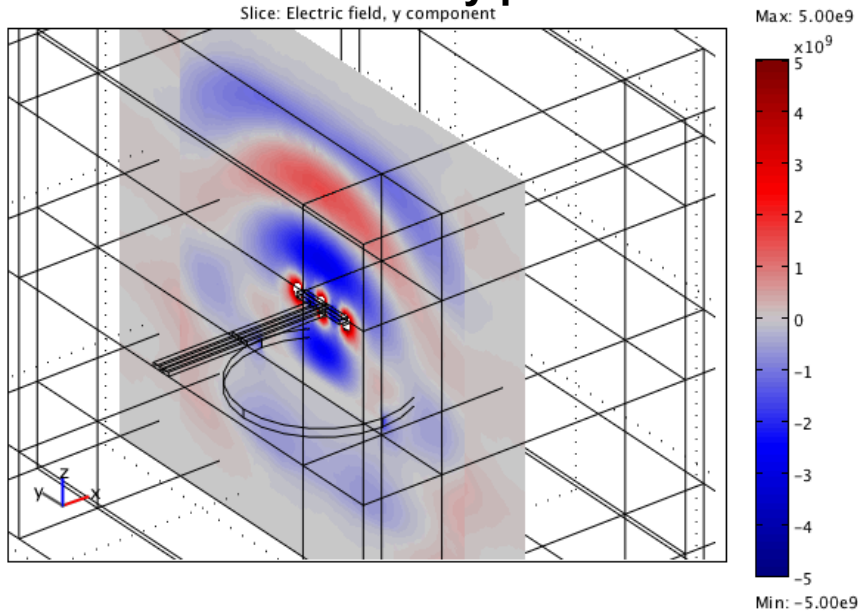
Key elements:

1. Integrated waveguide phase shifters
2. Plasmonic antenna arrays

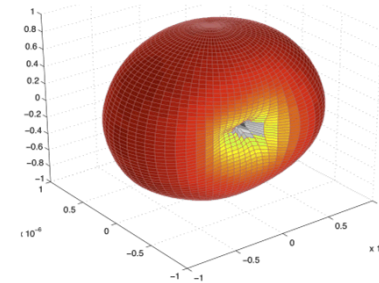


Radiation Pattern of MIM-fed Antenna

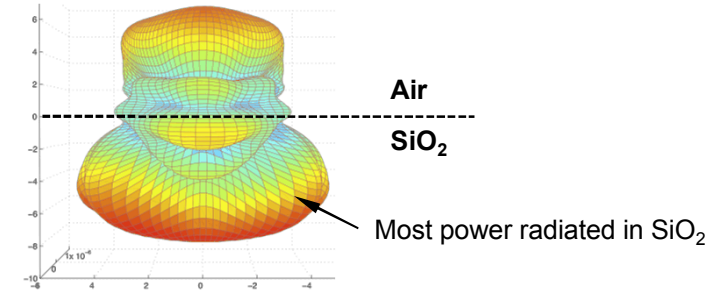
Surface-normal radiation by planar antennas



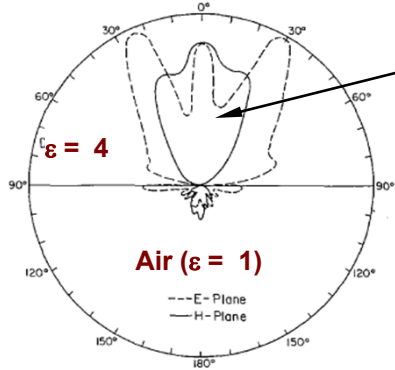
MIM-fed dipole in Air



MIM-fed dipole in on SiO₂ (No ground-plane)



Integrated antennas on high-index substrates

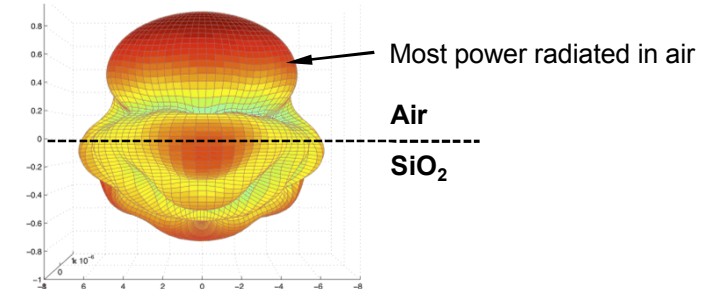


Most power radiated into substrate

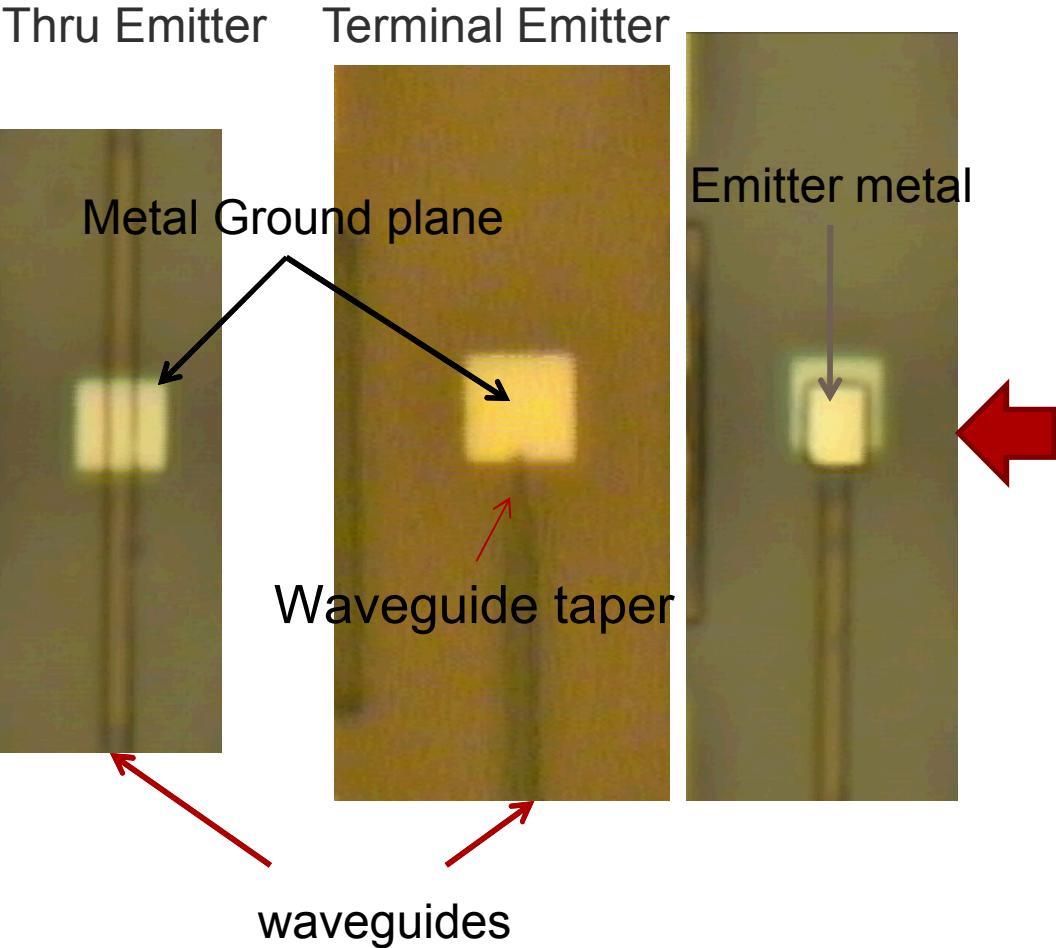
$$\frac{P_{\text{sub}}}{P_{\text{air}}} \sim \epsilon^{3/2}$$

Ground-plane is necessary !

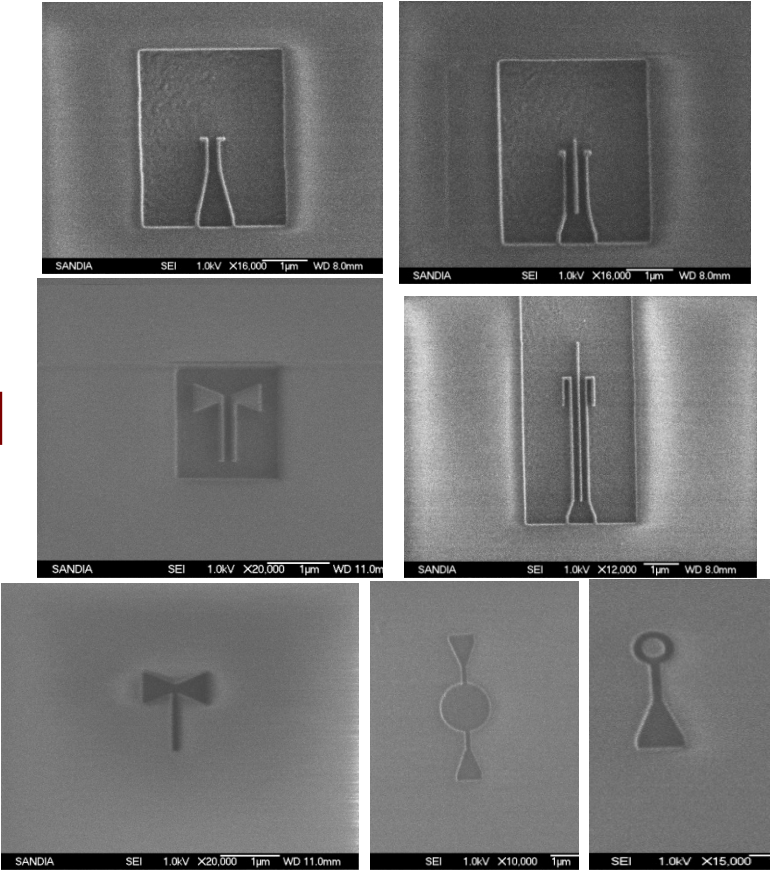
MIM-fed dipole in on SiO₂ (With ground-plane)



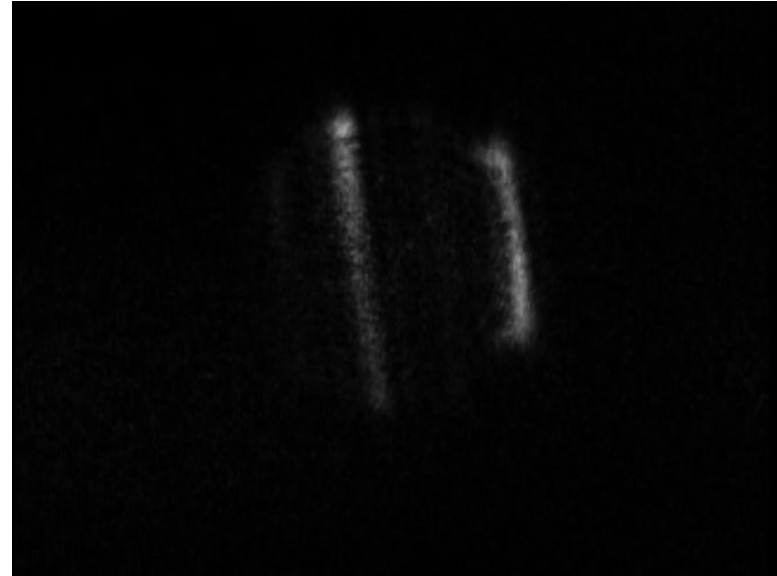
E-Beam Nanoantenna Template



E-Beam nanoantenna



Electronically Phase Controlled 1x8 Array

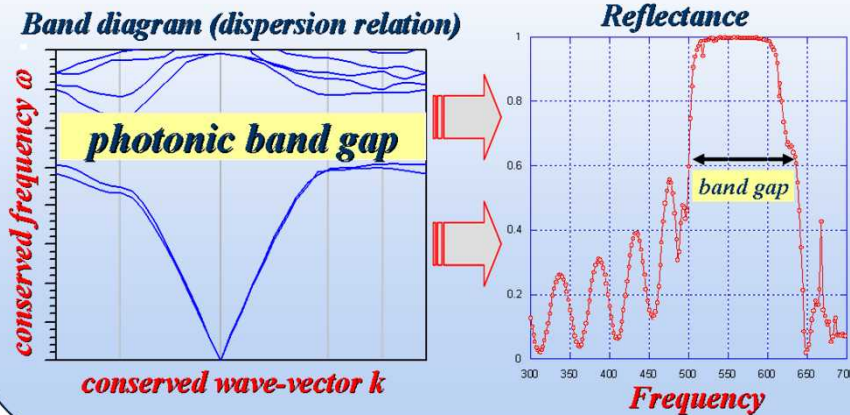


Demonstrated an optical phased array beam steering system comprised of

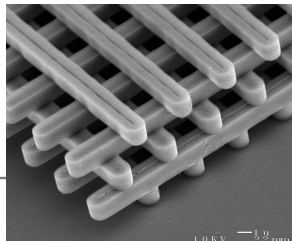
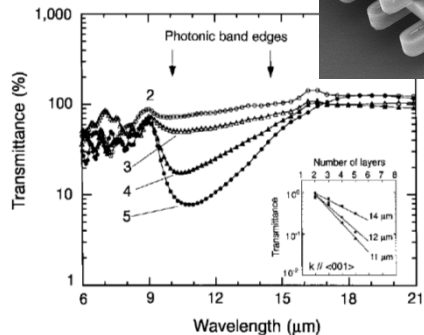
- Periodic array of plasmonic antennas
- Individually electronically addressed waveguide phase shifters (2π phase shift)
- Surface normal emission and steering at fixed wavelength.

Photonic Crystals (PhCs): Molding the Flow of Light at the Nano Scale

Photonic crystals create bandgaps where photons are forbidden to propagate.

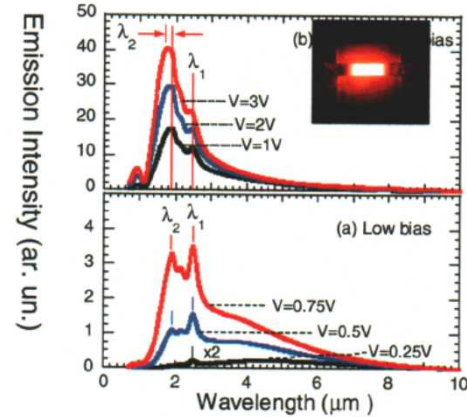
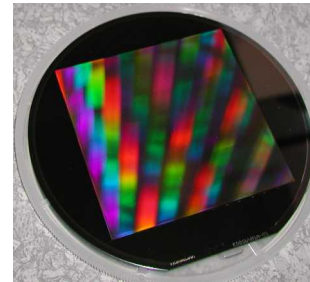


1st 3D Silicon PhC 1998-99



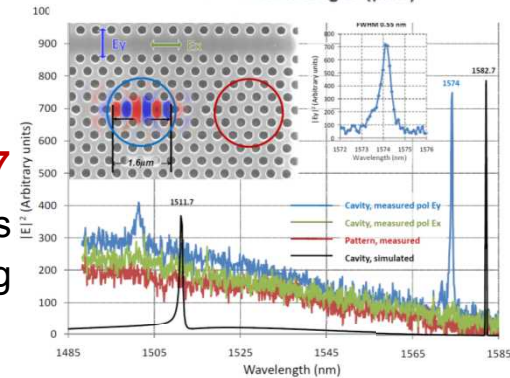
1st 3D IR Metallic PhC 2001-04

Tungsten PhC, Nature
Directional Emitters
PhC TPV App SNL



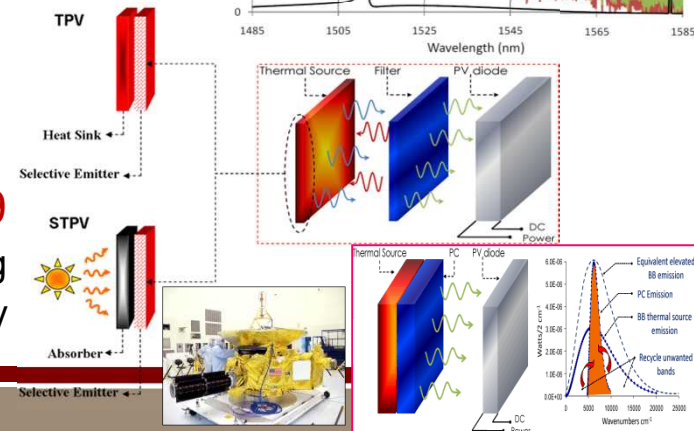
PhC Cavity QED 2007

Single photon sources
Quantum computing



PhC Near Field TPV 2009

Thermal Energy Harvesting
Renewable Energy

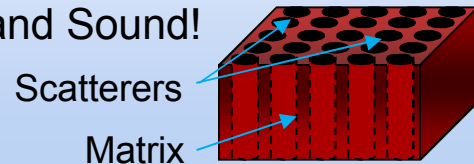


Phononic Crystals (PnCs):

Phonon Manipulation at the Micro and Nano Scale

Phonons (What?)

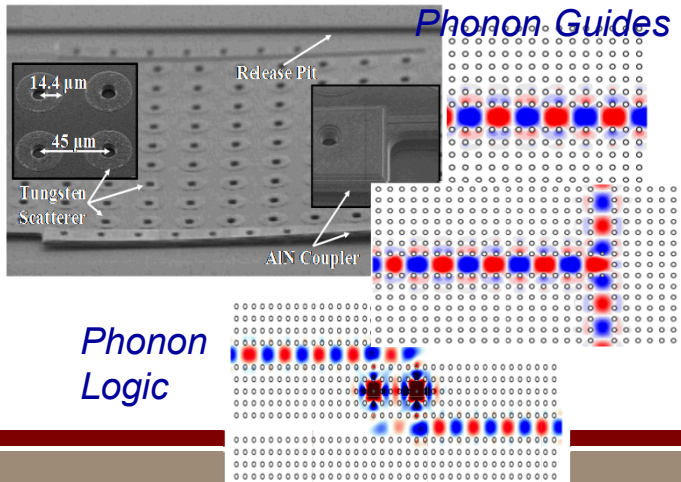
- The quantum mechanical rendering of lattice vibrations (normal modes)
- The quanta of mechanical oscillations
- Heat and Sound!



2007 1st MHz PnC

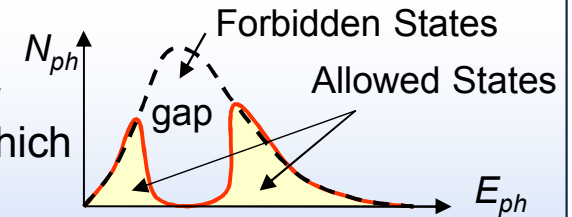
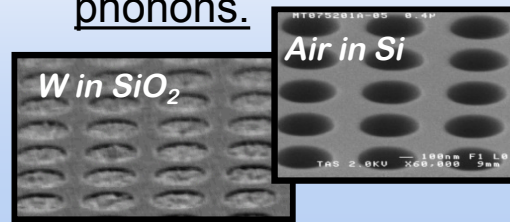
- Solid-Solid material sets
- RF Applications
- PnC-PhC Transformation

Phonon Guides



Phononic Crystals (How?)

Array of high impedance scattering centers in a low impedance background which exhibits stop bands for phonons.

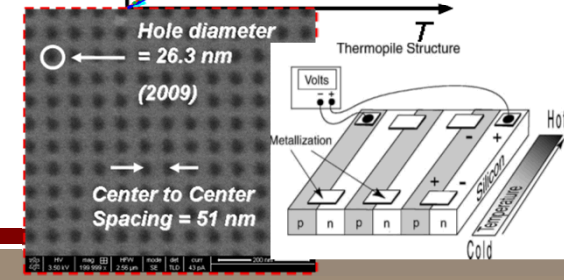
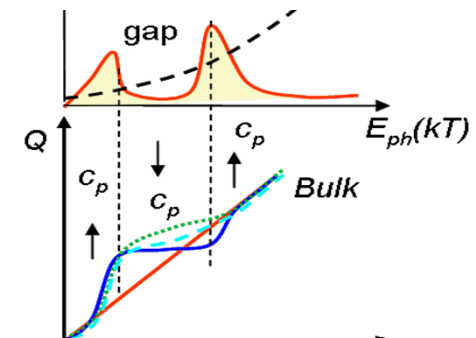
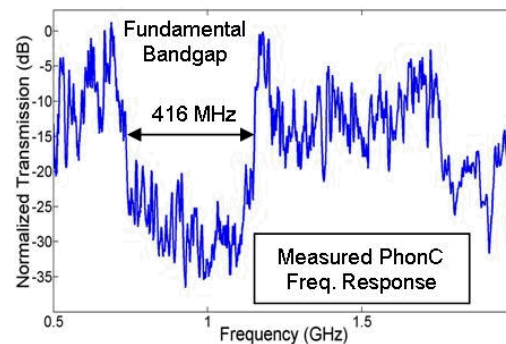


2009 1st THz PnC

- Engineer thermal properties
- Thermal management
- Thermal energy scavenging
- TE cooling

2008 1st GHz PnC

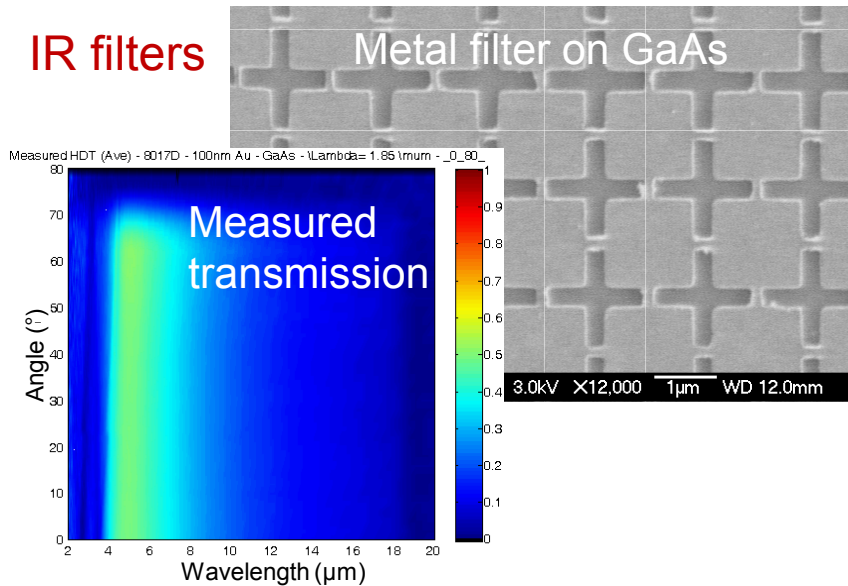
- Low loss RF devices and resonators
- RF communications, radars and spectral sensors



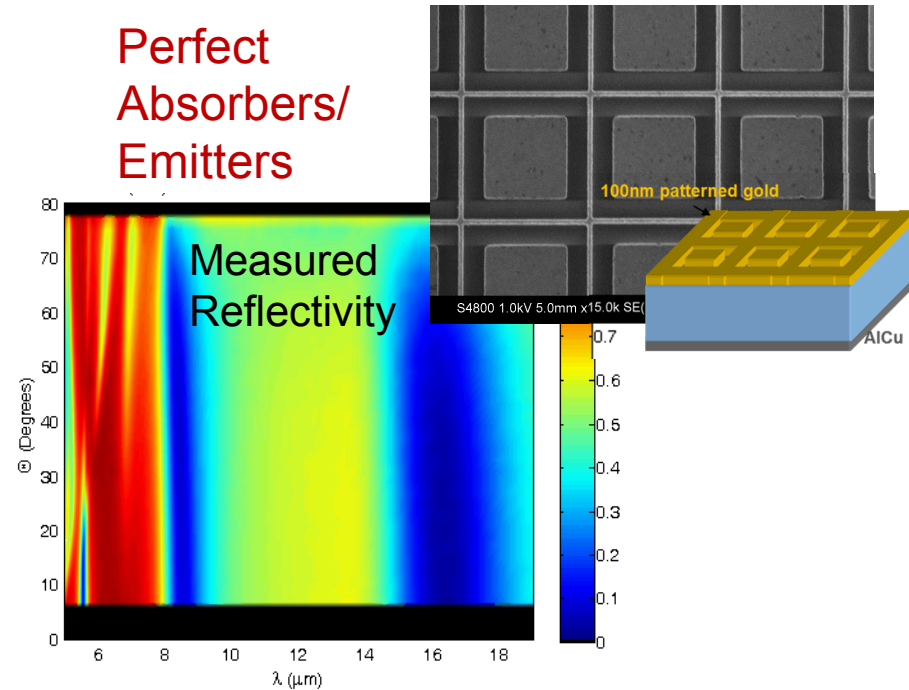
Planar Metallic Infrared Devices

Metal Optics for New Capabilities

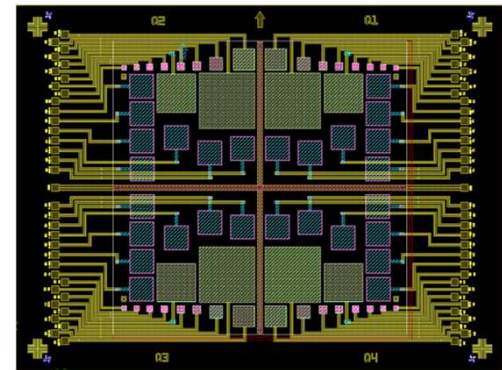
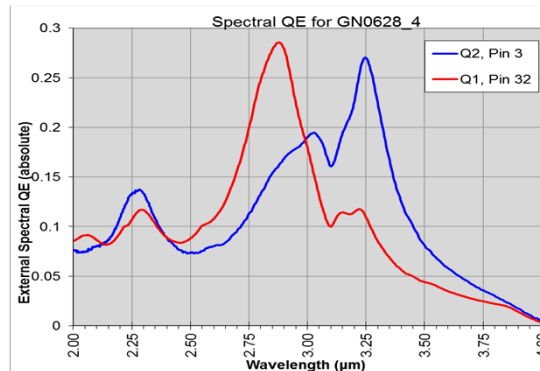
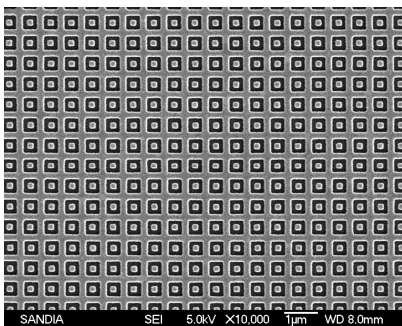
IR filters



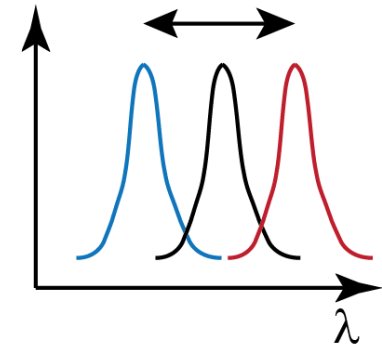
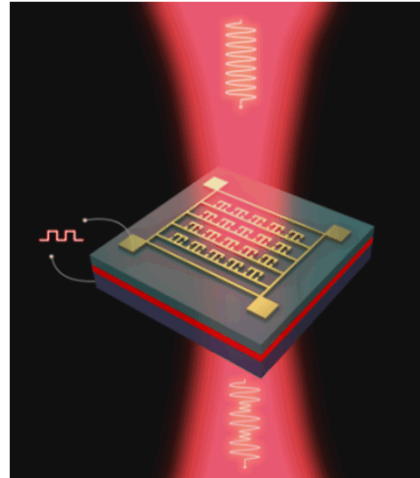
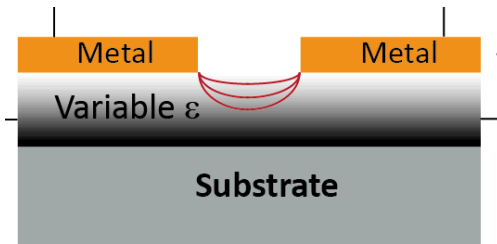
Perfect Absorbers/ Emitters



Next-Gen Low-Noise IR Detectors



Electrically Tunable Metamaterials for Agile Filtering in the Infrared



By controlling the interaction between planar metamaterials and semiconductors we created voltage tunable IR filters.

Specs:

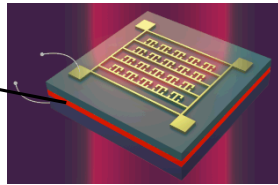
- Mid to long wave IR
- Pixel size: $5\mu\text{m}^2$ and up
- Tuning by 1-2 FWHM
- $Q \sim 10\text{-}20$
- Voltage $< 10\text{V}$
- Made from III-V semiconductors

PI: Igal Brener

Two Voltage-Controlled Tuning Mechanisms

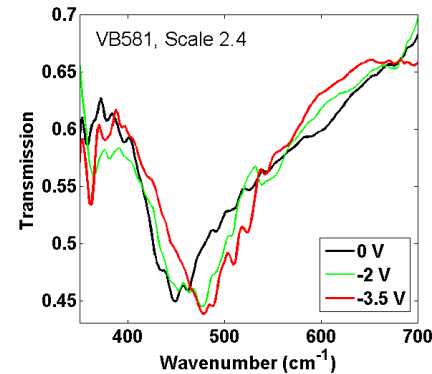
- Interaction with plasmons in highly doped semiconductor layers

n++, 20-40nm
(3e19 InGaAs, etc)

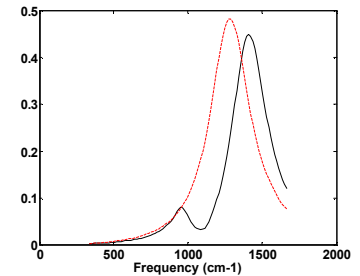


Nano Letters 13, 5391 (2013)

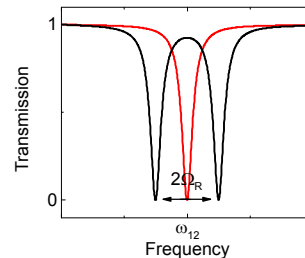
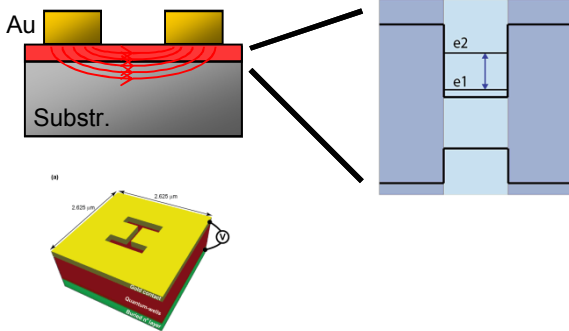
Preliminary results, long wave IR



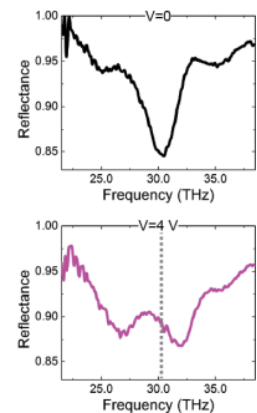
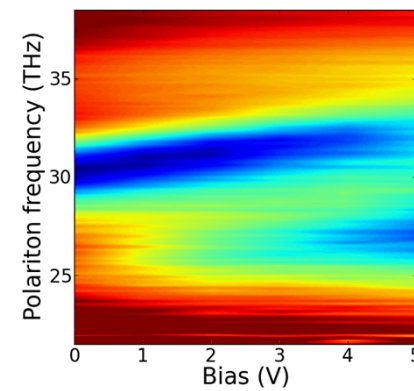
Recent modeling:



- Interaction with intersubband transitions in quantum wells



Preliminary results, thermal IR



Nature Communications 4, (2013) ; APL 103, 263116 (2013)

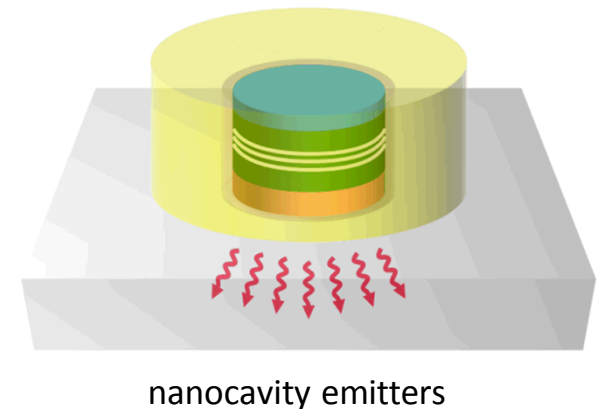
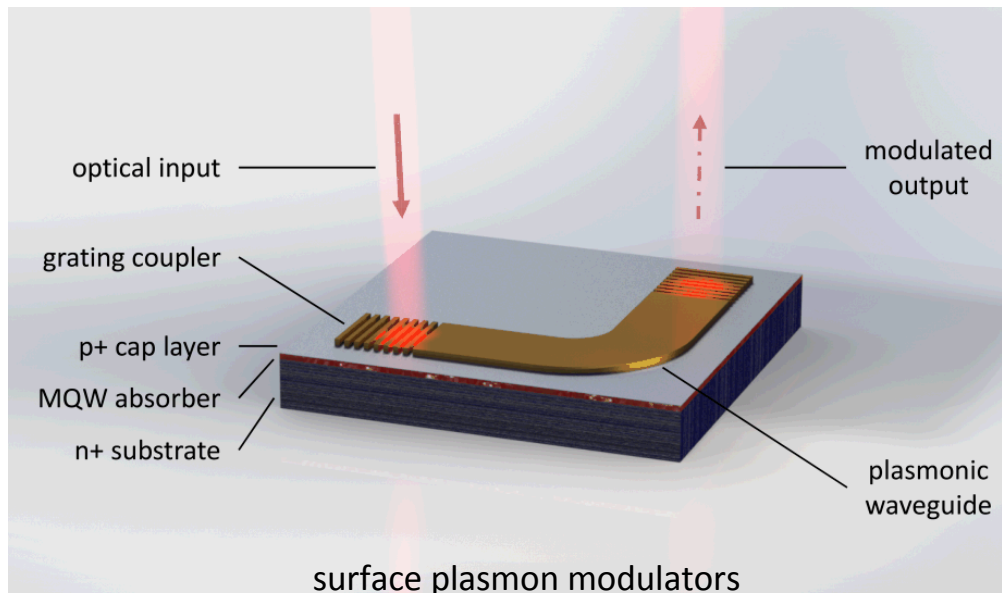
Near Infrared Active Plasmonics: Modulators, Emitters, Detectors

Plasmonics enables extreme field concentration and nanophotonic devices

- explosive field of study for the past decade (passive devices & MWIR/LWIR)
- devices promising for future photonic applications (speed, power, density)

Here we are investigating NIR active plasmonics in semiconductor materials

- leveraging strong resident photonics capabilities
- a wide range of practical devices that have not yet been explored



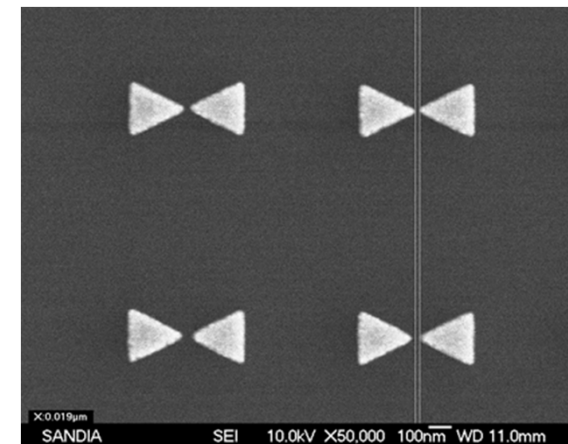
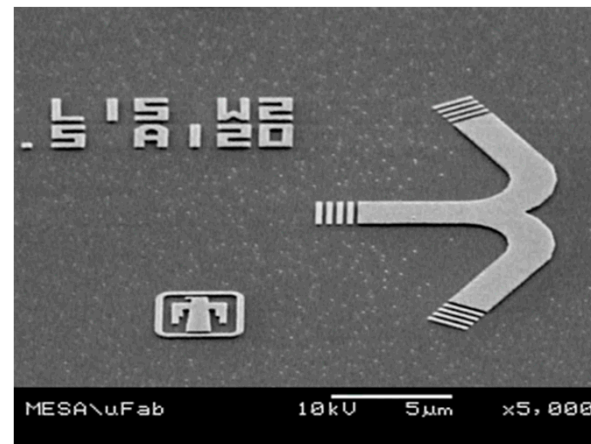
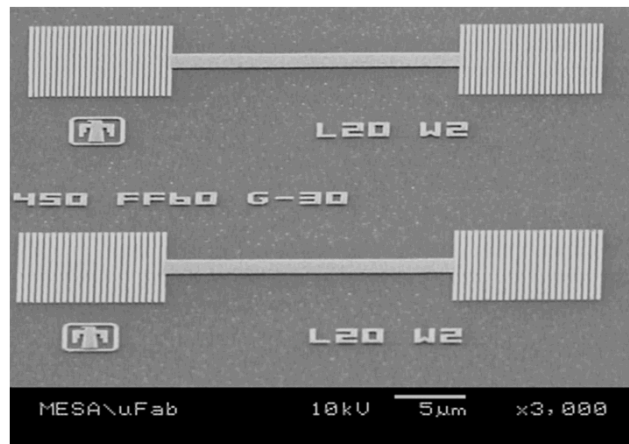
Nanofabrication of III-V Active Plasmonics

Growth and fabrication in Sandia's MESA and CINT nanofabrication facilities

- epitaxial growth on GaAs, GaSb, and InP by MBE and MOCVD
- patterning using a combination of contact and e-beam lithography
- standard III-V processing using wet/dry etch, metallization, anneal, etc.

Nanoscale devices under study

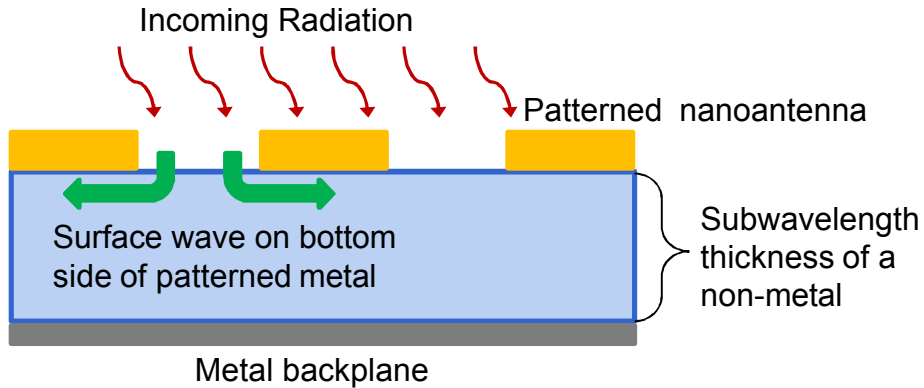
- modulators, nanoemitters, plasmonic crystals
- surface-normal grating couplers with varying fill factor, pitch, thickness
- waveguide bends, splits, dot waveguides, concentrators, gap antennas



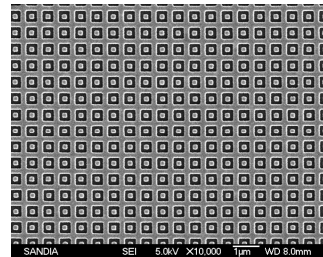
active nanoplasmonic devices fabricated on compound semiconductors

Nanoantenna-Enabled Thin Detectors

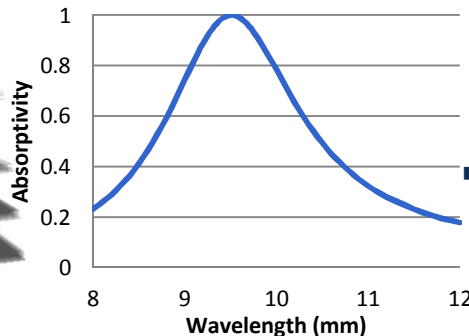
What is a nanoantenna?



Incident IR radiation



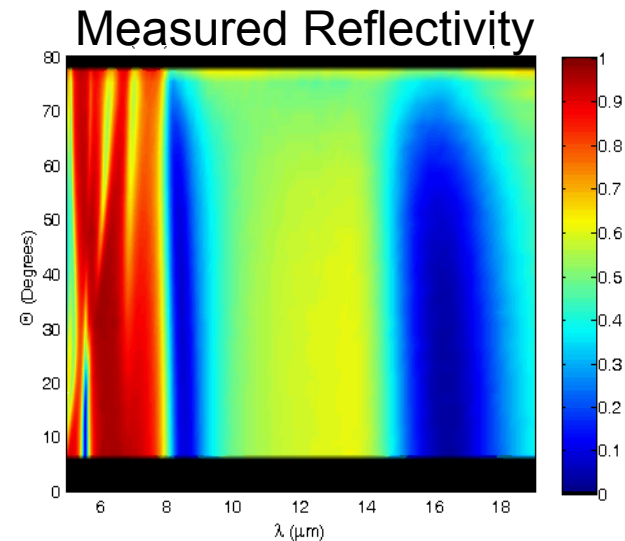
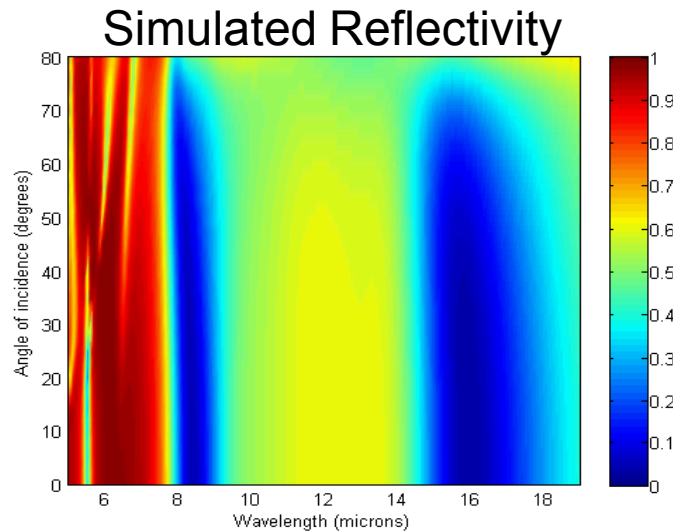
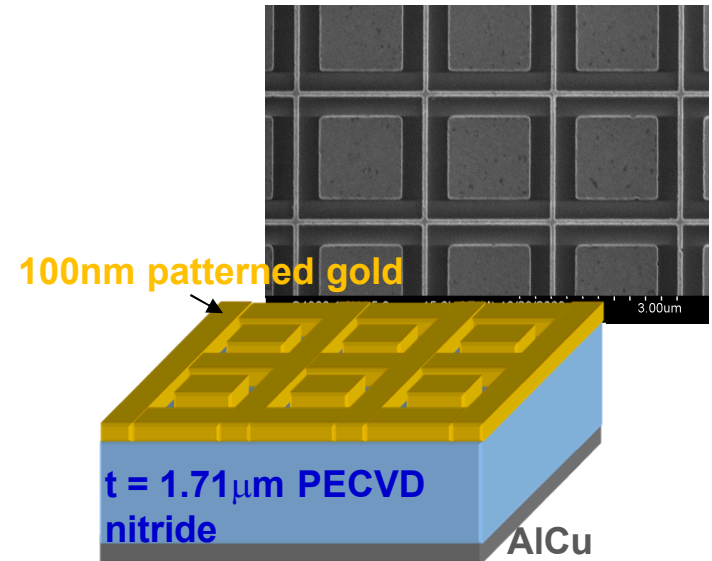
High-intensity surface wave



- Nanoantennas are a fundamental technology that spans numerous sensor types
- Nanoantennas are an enabling technology for new applications such as 2D materials
- A nanoantenna is a distributed energy conversion device: the entire surface is the device
- A nanoantenna converts incoming radiation to a surface wave with energy confined to a small volume under the nanoantenna
- This confinement is what enables us to look at interesting applications
- The pattern is subwavelength, with many nanoantenna periods per device pixel. This pattern may be changed on a pixel-to-pixel basis allowing adjacent pixels to have different spectral or polarization response
- Our IR devices are enhanced by, or completely reliant on, the radiation conversion achieved by the nanoantenna

Background: Perfect Absorbers

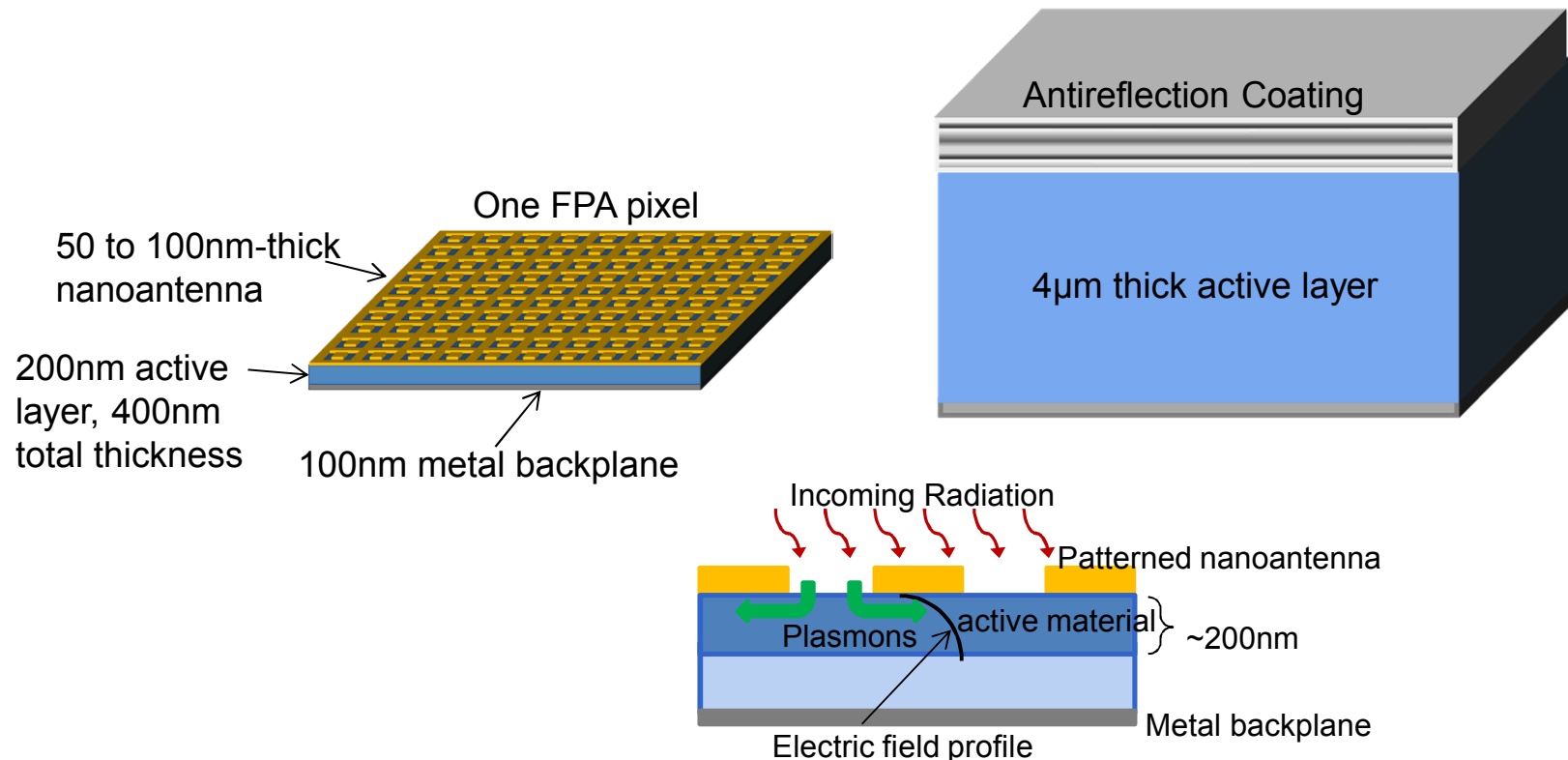
- We designed and made a dual-band perfect absorber.
- Excellent agreement between simulation and measurement → Great confidence in our models.
- Measured absorption of 99% in two bands.
- If we can absorb it, why not use that energy?



Incorporation with Existing Detector Materials in the Midwave

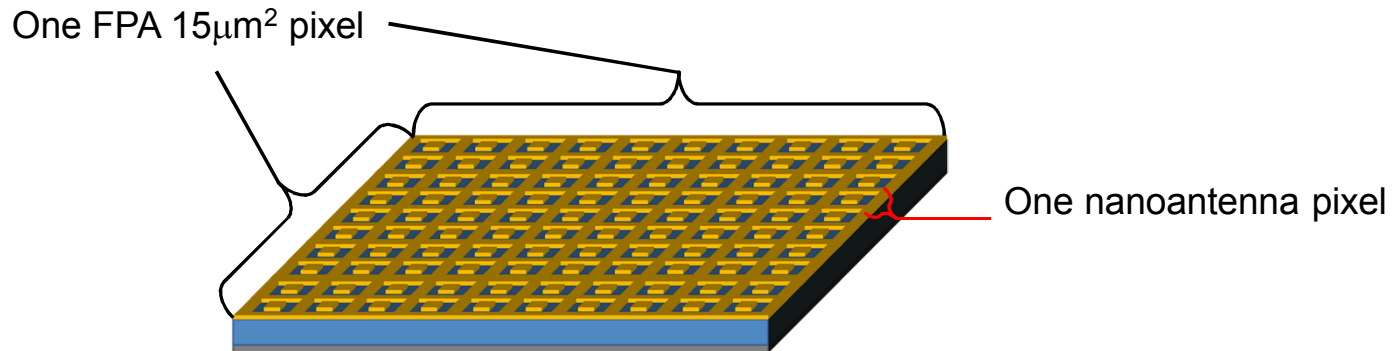
Integrate subwavelength nanoantenna with active material (MCT or InGaSb) for high-performance focal plane array (FPA).

Using dense fields to thin the active region.

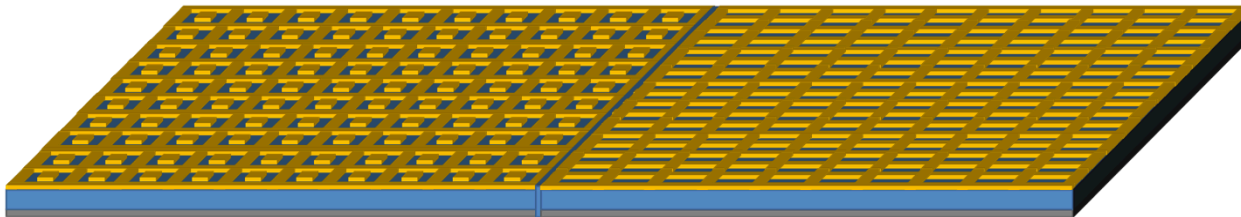


Advantages of the Nanoantenna Structure

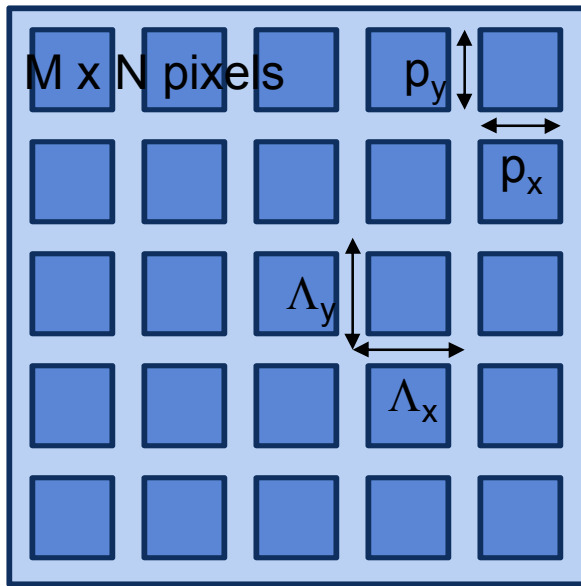
- Top and bottom contacts allow direct connection.
- Filtering can be changed from FPA pixel-to-pixel simply by changing the antenna pattern (Spectral or polarization). This is difficult to do with thin films.
- Small antenna unit cell allows multiple unit cells per FPA pixel (for broadband).



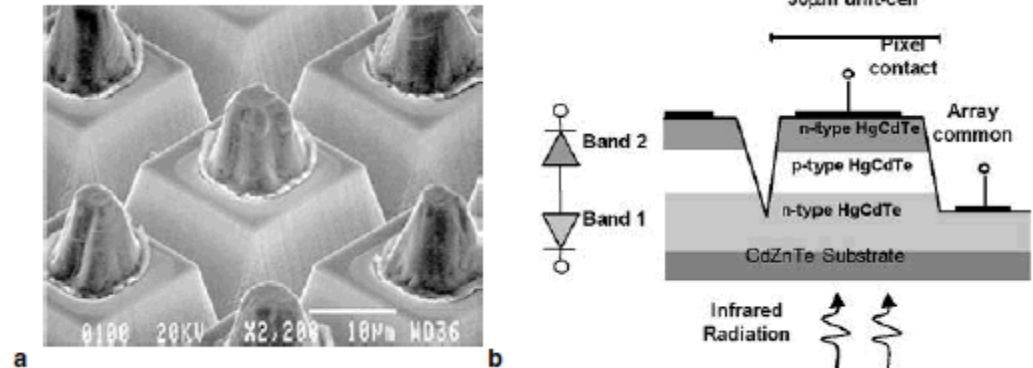
Two adjacent FPA pixels with different functionality.



Maximizing Active Area Improves MTF and Signal Sandia National Laboratories

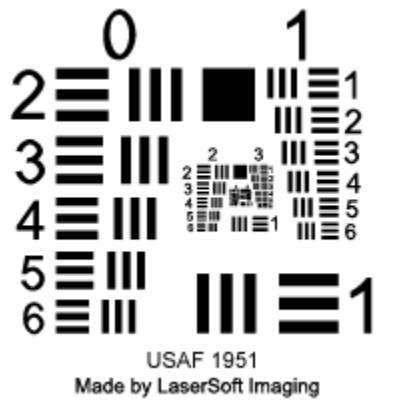


MCT FPA architecture



from E.P.G. Smith, et al, *J. of Electr. Matl.*, 2004.

$$\text{MTF}(f_x, f_y) = [\text{sinc}((M \cdot \Lambda_x) \cdot f_x, (N \cdot \Lambda_y) \cdot f_y) * \text{comb}(\Lambda_x \cdot f_x, \Lambda_y \cdot f_y)] \cdot \text{sinc}(p_x \cdot f_x, p_y \cdot f_y)$$



Ideally for the mathematical MTF function, we want Λ_x , Λ_y and p_x , p_y as small as possible to maximize the MTF.

This is clearly impossible, but we can make Λ_x and Λ_y as small as possible for a given p_x and p_y .

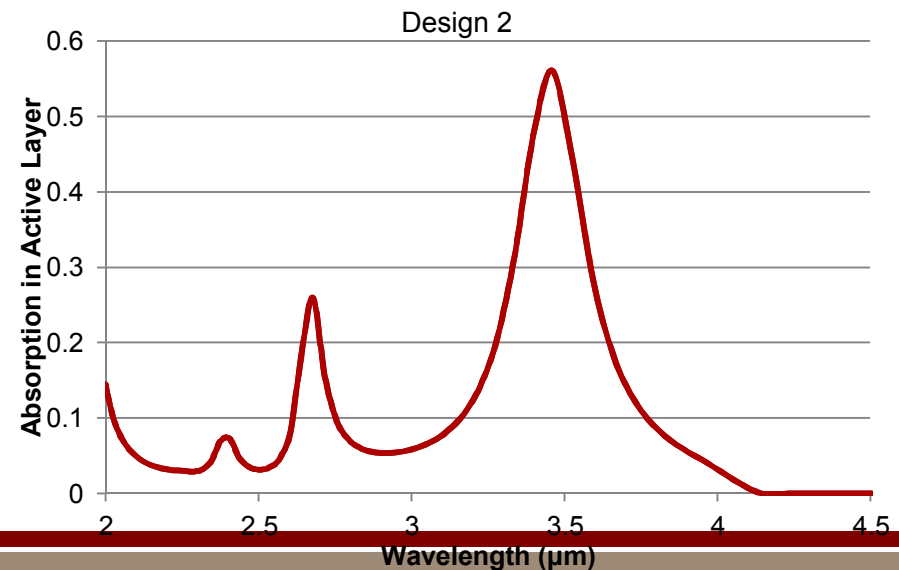
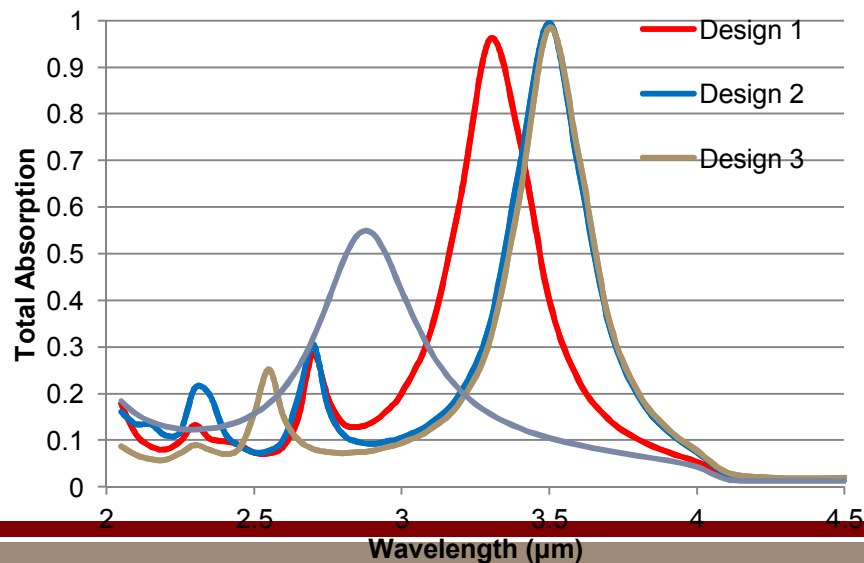
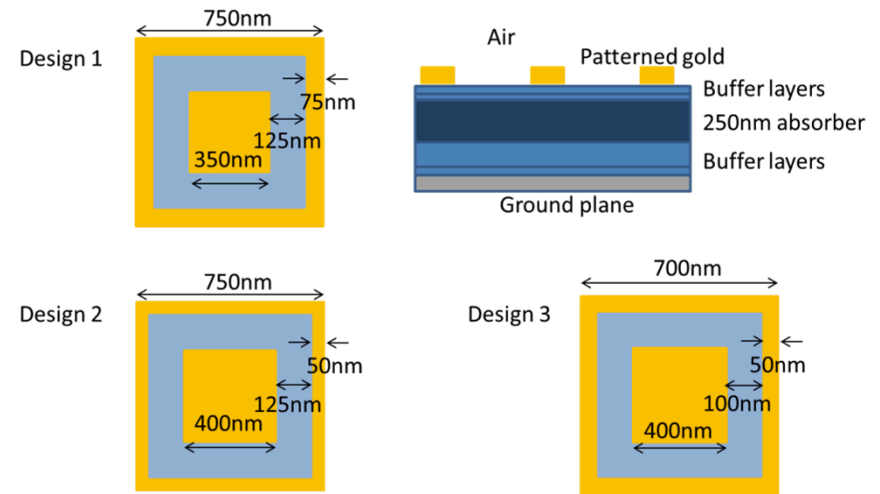
Our architecture gives us near 100% fill factor.

Simulation of InAsSb Design

Designs for peak responsivity in the $3.25\mu\text{m}$ to $3.5\mu\text{m}$ range.

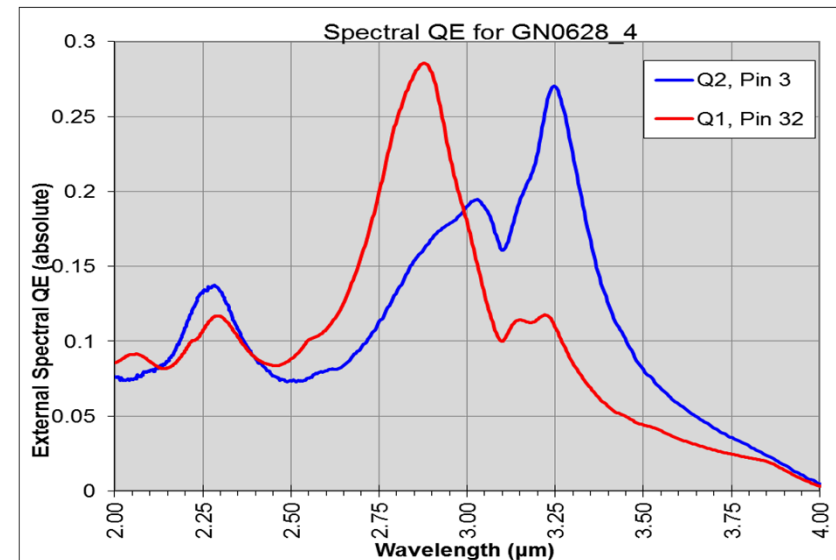
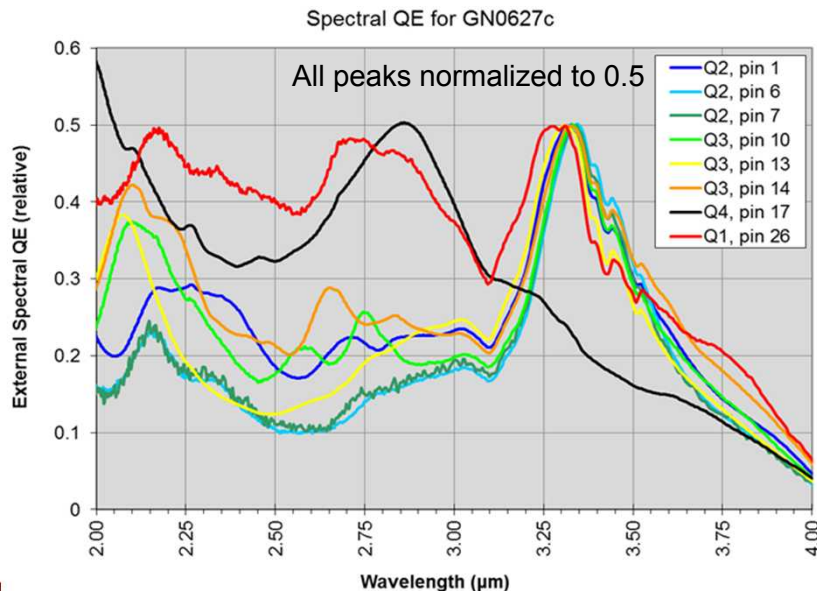
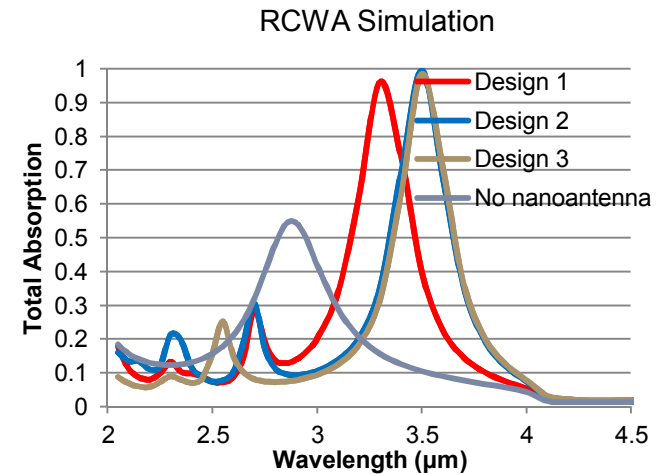
Three designs were fabricated with different patterns but similar peak resonances.

Designs were not optimized to maximize absorption in the active layer.



Nanoantenna-Enhanced InAsSb Detector Results

- Epitaxial growth of two designs for integration with NA for test/ evaluation.
- Successful fabrication of detectors with integration of NAs using a flip-chip bonding process and selective substrate removal.
- Room for optimization in modeling and in characterization procedures.

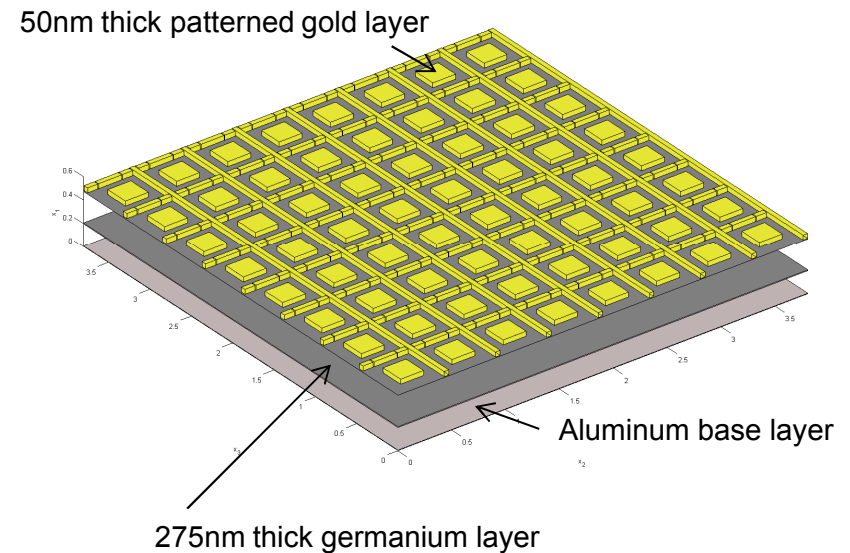
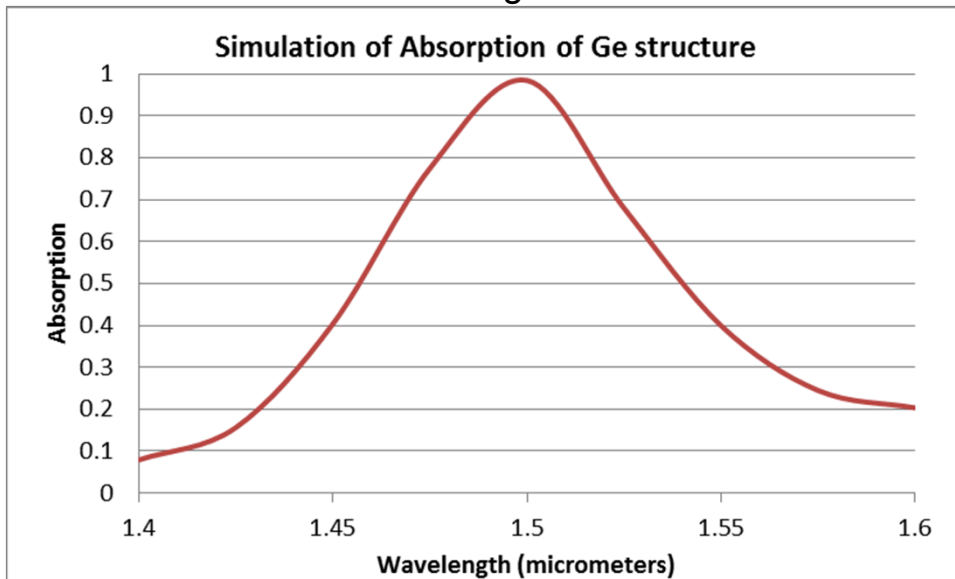
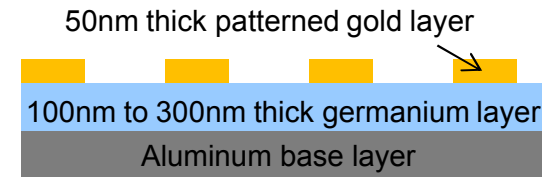


Germanium Detector

As with the MWIR designs, this one involves a detection material between two metal layers. Since it is for the near-IR, the detector layer is quite thin. The metal top and bottom layers act as contacts.

As it is thin, it is very fast as carriers move to a metal electrode quickly. Since the metal wire grid is not a large solid piece of metal, the capacitance should also be low.

We designed and simulated a structure with dimensions below to work at $1.5\mu\text{m}$. This is in the telecommunications wavelength band.



Period of nanoantenna = 475nm
Width of continuous gold bars = 50nm

Germanium Detector Design

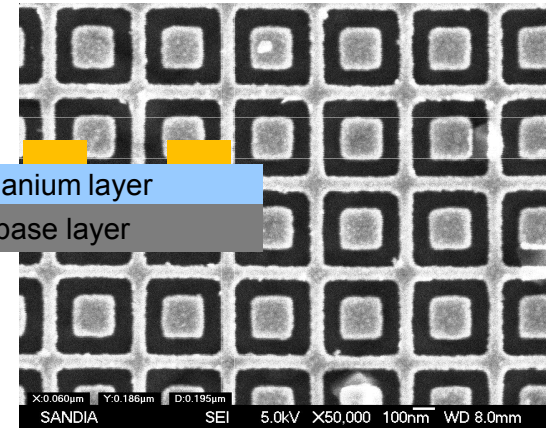
There is virtually no change from normal out to 40° in the 100nm thick design. In any practical imaging system, this is more than enough.

In the 275nm-thick design we see a change in peak wavelength between 20° and 30° .

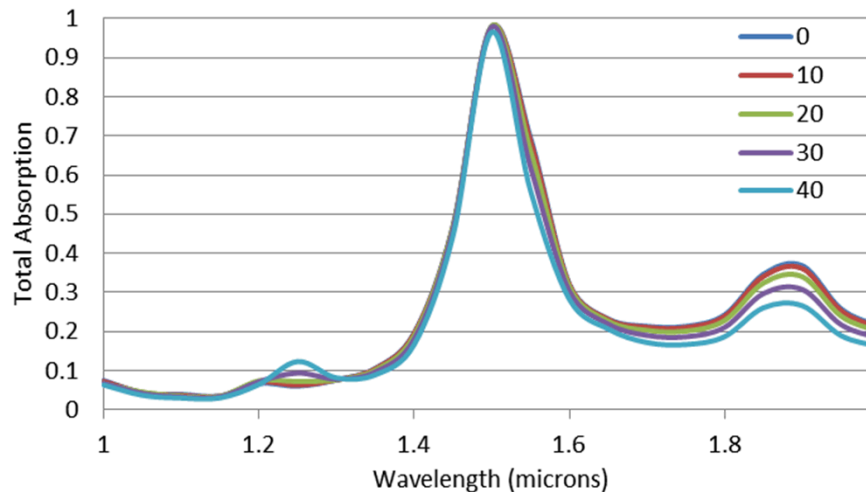
50nm thick
patterned gold
layer

100nm germanium layer

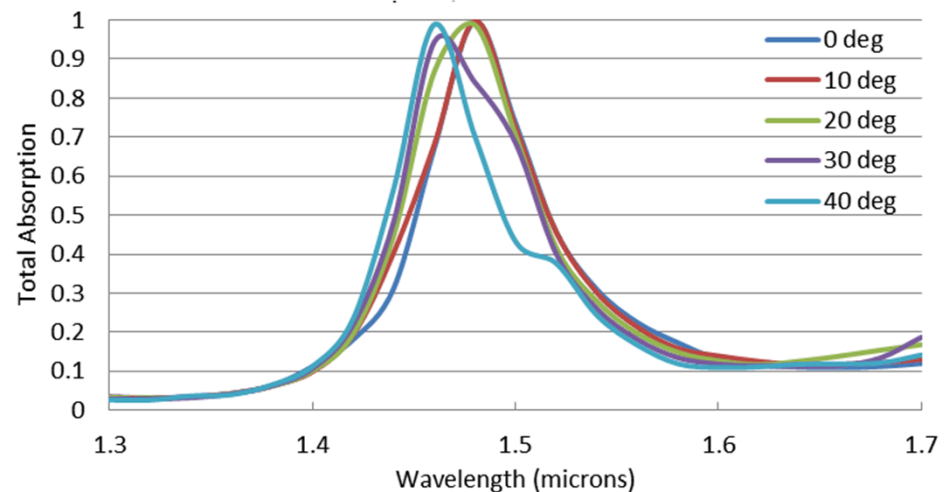
Aluminum base layer



Function of angle: 100nm Ge layer, 400nm period



Function of angle: 275nm Ge layer, 450nm period



Graphene Detectors: Bilayer Graphene Tunability

nature

Vol 459 | 11 June 2009 | doi:10.1038/nature08105

LETTERS

Direct observation of a widely tunable bandgap in bilayer graphene

Yuanbo Zhang^{1*}, Tsung-Ta Tang^{1*†}, Caglar Girit¹, Zhao Hao^{2,4}, Michael C. Martin², Alex Zettl^{1,3}, Michael F. Crommie^{1,3}, Y. Ron Shen^{1,3} & Feng Wang^{1,3}

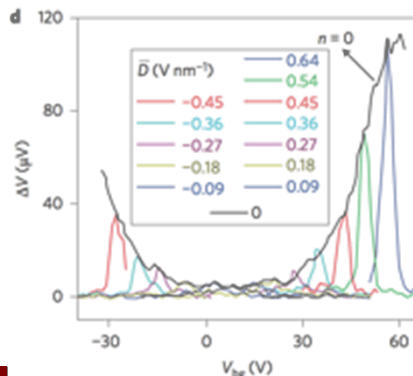
ARTICLES

PUBLISHED ONLINE: 3 JUNE 2012 | DOI: 10.1038/NNANO.2012.88

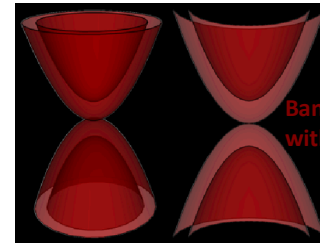
nature
nanotechnology

Dual-gated bilayer graphene hot-electron bolometer

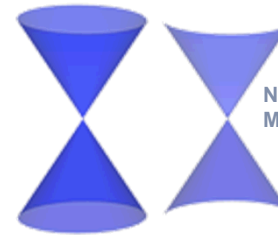
Jun Yan^{1,2}, M.-H. Kim^{1,2}, J. A. Elle^{2,3}, A. B. Sushkov^{1,2}, G. S. Jenkins^{1,2}, H. M. Milchberg^{2,3}, M. S. Fuhrer^{1,2*} and H. D. Drew^{1,2}



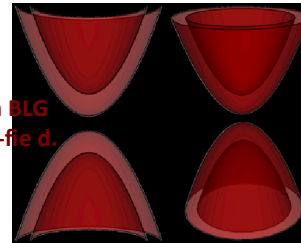
BLG: E-Field=0



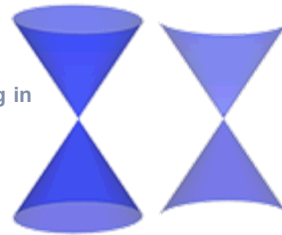
Mono: E-Field=0



BLG: E-Field>0



Mono: E-Field>0



Bandgap opens in BLG with transverse E-field.

No bandgap opening in MLG with E-field

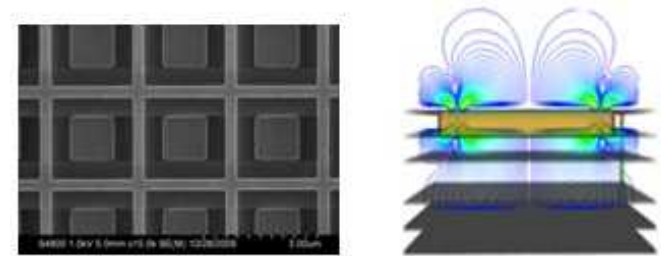
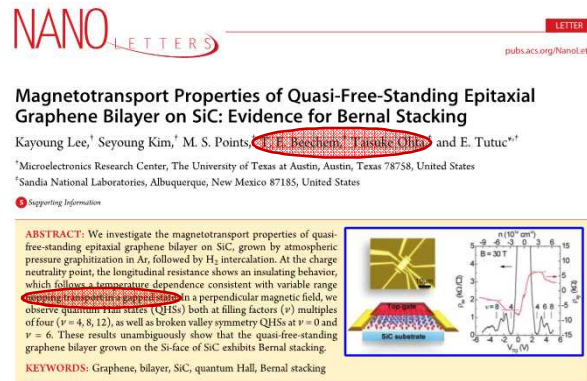
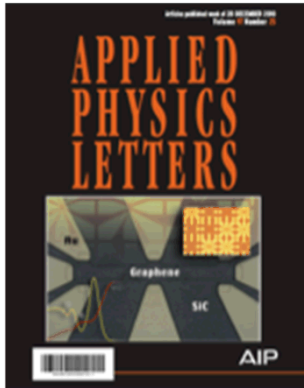
Problems:

1. Scalability
2. Low absorption
3. Multiphysics problem

Approach: Combination of Technologies

Scalability: Wafer-Scale BLG

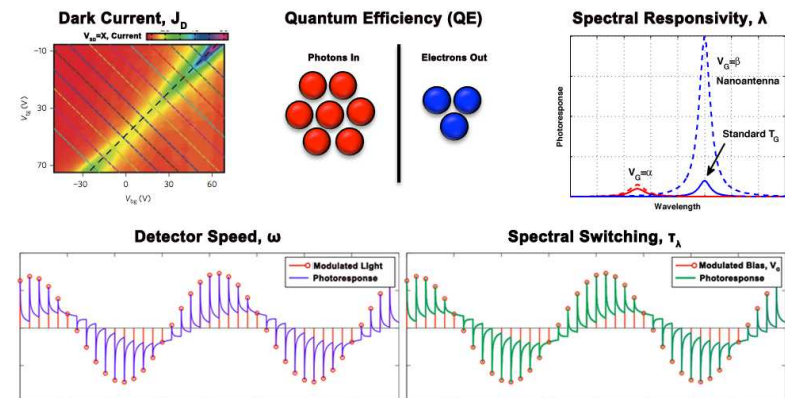
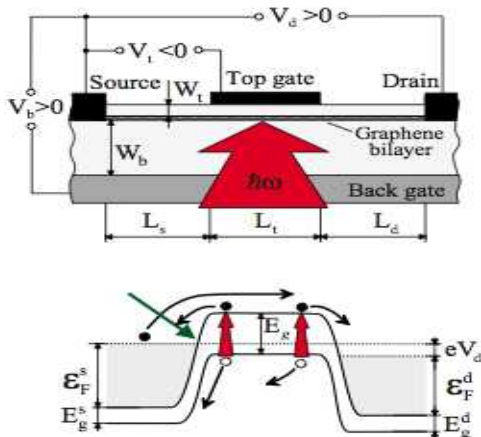
Low Absorption: Nanoantennas



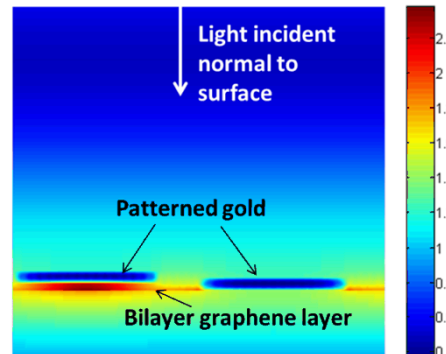
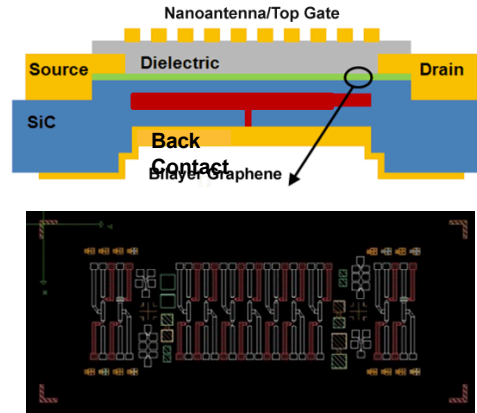
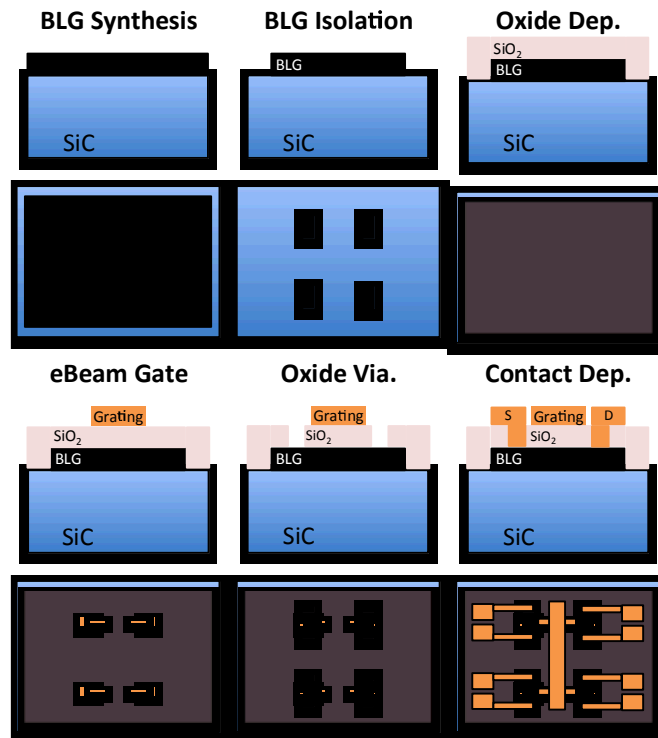
Nanoantenna-Enabled Midwave Infrared Focal Plane Arrays
 David W. Peters*, Charles M. Reinke, Paul S. Davids, John F. Klem, Darin Leonhardt, Joel R. Wendt, Jin K. Kim, Sally Samora
 Sandia National Laboratories, P.O. Box 5800, Albuquerque, NM, USA 87185-1082
 Proc. of SPIE Vol. 8353 83533B-1

Phenomenon: PhotoFET

Next Steps: Technology Maturation

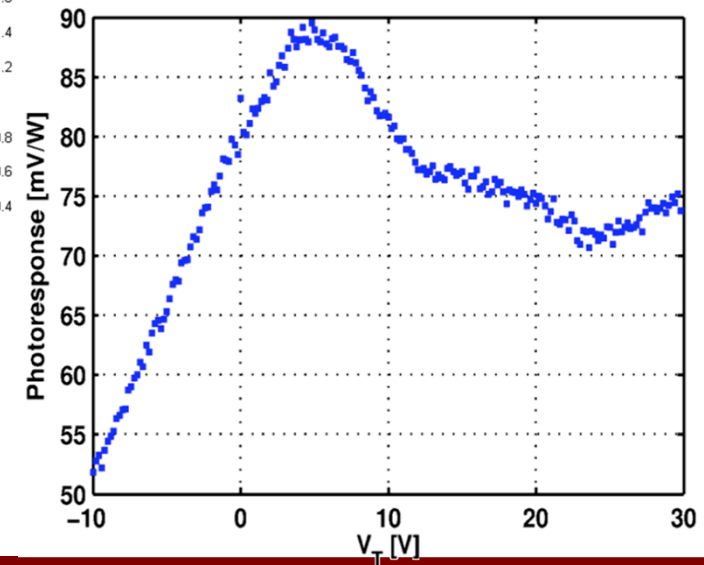


Graphene Detector: Early Fab and Results



- Scalable fabrication using “standard” techniques
- Multiple operational devices on a chip
- Opens path towards arrays
- Developed an improved understanding of the graphene/SiC interface

Devices show bias dependent tunability with a signal enhanced by nanoantennas.



Nanophotonics is an integral part of Sandia MESA research and fabrication.

- Plasmonic devices.
- Infrared detectors.
- New materials such as graphene and pyrolyzed carbon.

Nanoantennas offer methods of enhancement in traditional and new detector platforms.

- InAsSb detectors in the MWIR.
- Germanium detectors in the Near-IR.
- Graphene detectors that offer new capabilities.

Extra Slides

Si Photonics Publications in FY14

- J. A. Cox, A.L. Lentine, Douglas C. Trotter, and Andrew L. Starbuck, "Control of integrated micro-resonator wavelength via balanced homodyne locking," *Opt. Express* **22**, 11279-11289 (2014)
- R. Aguinaldo, A. Forencich, C. DeRose, A. Lentine, D. C. Trotter, Y. Fainman, G. Porter, G. Papen, and S. Mookherjea, "Wideband silicon-photonics thermo-optic switch in a wavelength-division multiplexed ring network," *Opt. Express* **22**, 8205-8218 (2014)
- J. A. Cox, A.L. Lentine, D. J. Savignon, R. D. Miller, D. C. Trotter, and A. L. Starbuck, "Very Large Scale Integrated Optical Interconnects: Coherent Optical Control Systems with 3D Integration," in *Advanced Photonics for Communications*, OSA Technical Digest (online) (Optical Society of America, 2014), paper IM2A.1.
- C. DeRose, "Integrated RF Silicon Photonics from High Power Photodiodes to Linear Modulators," in *Advanced Photonics for Communications*, OSA Technical Digest (online) (Optical Society of America, 2014), paper IW2A.1.
- D.A. Bender ; C. T. DeRose ; A. Starbuck ; J. C. Verley and M. W. Jenkins, "Precision laser annealing of silicon devices for enhanced electro-optic performance", *Proc. SPIE 8967*, Laser Applications in Microelectronic and Optoelectronic Manufacturing (LAMOM) XIX, 89670S (March 6, 2014).
- J. A. Cox, A. L. Lentine, D. J. Savignon, D. Trotter, and A. Starbuck, "Wavelength Control of Resonant Photonic Modulators with Balanced Homodyne Locking," in *CLEO: 2014*, OSA Technical Digest (online) (Optical Society of America, 2014), paper STh4M.7.
- C.T. DeRose, R. Kekatpure, A. Starbuck, A. Pomerene and A. L. Lentine, "A CMOS Compatible External Heater-Modulator", IEEE Opt. Interconnect Conf., MC3, pp.17-18, May 2014.
- C.T. DeRose, N.J. Martinez, R.D. Kekatpure, W.A. Zortman, A.L. Starbuck, A. Pomerene and A. L. Lentine, "Thermal Crosstalk Limits for Silicon Photonic DWDM Interconnect", IEEE Opt. Interconnect Conf., WC5, pp.125-126, May 2014.
- T. Iatchu, M. Pochet, N.G. Usechak, C. DeRose, A. L. Lentine, D.C. Trotter, and W. Zortman, "Power-Penalty Comparison of Push-Pull and Traveling-Wave Electrode Silicon Mach-Zehnder Modulators", IEEE Opt. Interconnect Conf., MC7, pp.25-26, May 2014.
- R. Aguinaldo, A. Forencich, C. DeRose, A. L. Lentine, A. Starbuck, Y. Fainman, G. Porter, G. Papen, S. Mookherjea, "Characterization of a silicon-photonics wideband switch in UCSD's MORDIA ring network", IEEE Opt. Interconnect Conf., TuD4, pp.102-103, May 2014.
- R. Aguinaldo, P.O. Weigel, H. Grant, C. DeRose, A. L. Lentine, A. Pomerene, A. Starbuck, S. Mookherjea, "Characterization of a silicon-photonics multi-wavelength power monitor", IEEE Opt. Interconnect Conf., WD5, pp.139-140, May 2014.
- 2 at Integrated Photonics Research Conf., 5 at Optical Interconnect Conf., 1 SPIE, 1 CLEO; 2 journals.

Selected Sandia's Photonics Patents

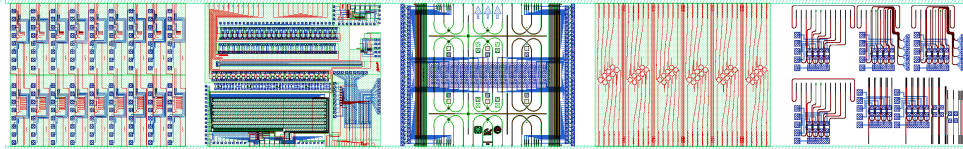
Silicon Photonics

- U.S. Patent 7616850, Wavelength-Tunable Optical Ring Resonators (SD 10791.0)
- U.S. Patent 7941014, Optical Waveguide Device With An Adiabatically-Varying Width (SD 11104.0)
- U.S. Patent 7983517, Wavelength-Tunable Optical Ring Resonators (SD 10791.1)
- U.S. Patent 8027587 , Integrated Optic Vector-Matrix Multiplier(SD 10237.1)
- U.S. Patent 8610994, Silicon Photonics Thermal Phase Shifter With Reduced Temperature Range (SD 11837.0)
- U.S. Patent 8615173, Systems For Active Control of Integrated Resonant Optical Device Wavelength (SD 11555.0)
- U.S. Patent 8600200, Nano-Optomechanical Transducer (SD 11508.0)
- U.S. Patent 8625939, Ultralow Loss Cavities and Waveguides Scattering Loss Cancellation (SD 11631.0)
- U.S. Patent 8822959, Method And Apparatus For Optical Phase Error Correction (SD 12024.0)

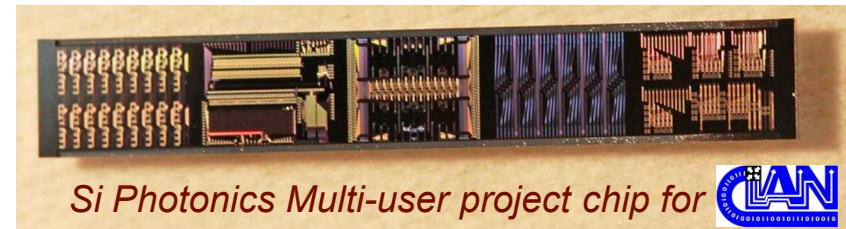
Plasmonics for Infrared Sensors

- U.S. Patent 8452134, Frequency Selective Infrared Sensors (SD 11433.0)
- U.S. Patent 8750653, Infrared Nanoantenna Apparatus and Method for the Manufacture thereof (SD 12379.0, SD 12539.0)
- 9 issued patents in Si photonics and 2 in nano-antenna related areas (4 issued in FY2014)
- 21 additional patents pending (9 patents filed in FY2014)

SiP Multi-User Wafer Project



Cornell UCSD Berkeley Arizona Berkeley

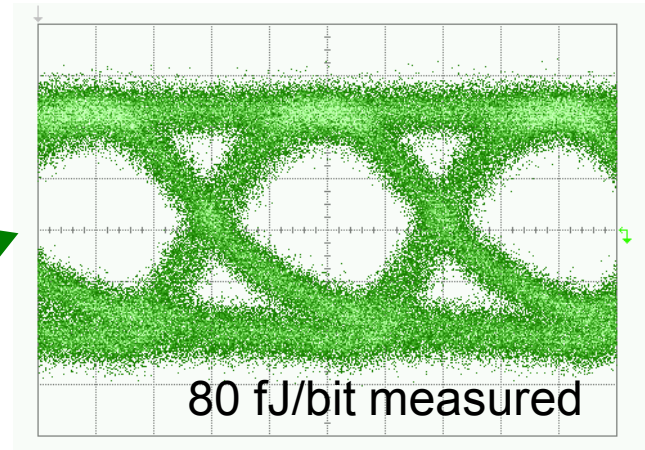
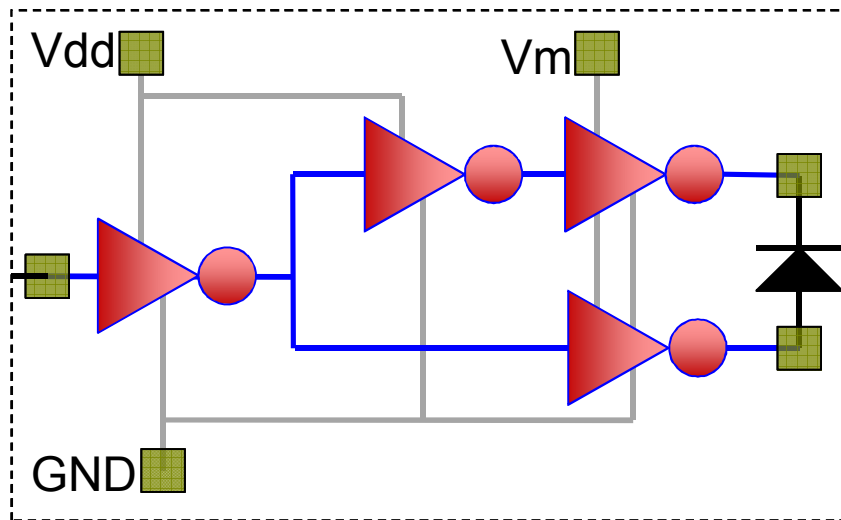
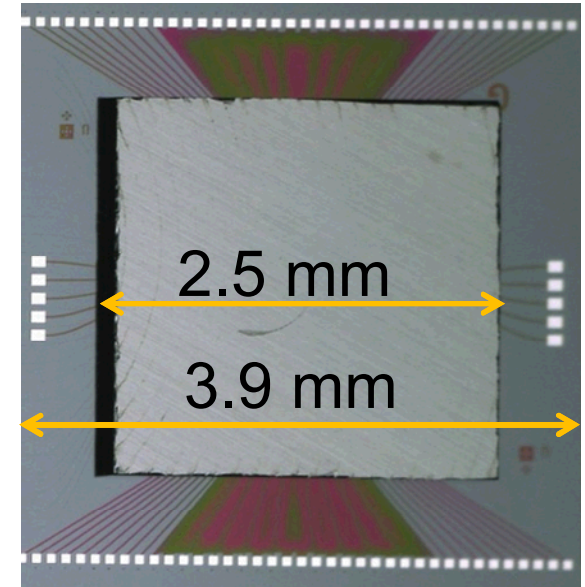
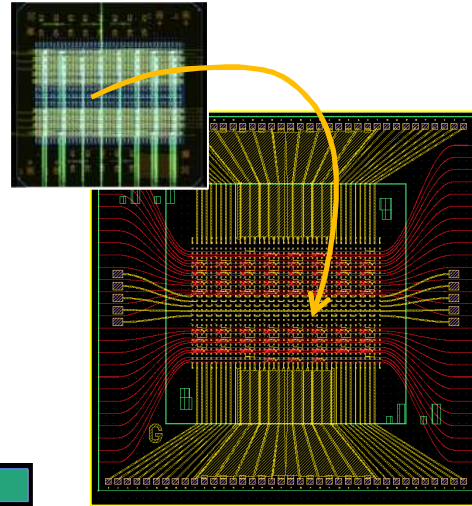
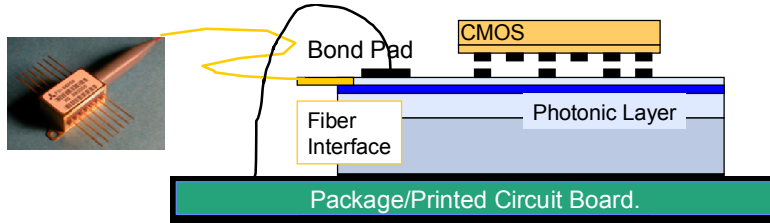


- Successfully completed 3 milestone deliverables to NSF CIAN (Center of Integrated Access Networks) universities
 - Passive chips
 - Active chips (with P/N junctions for modulators, etc.)
 - Active chips with Germanium (with integrated photo detectors)
- On-going discussions for next collaborations (to include CUDOS and University of Bristol)
- Active planning in Photonics Manufacturing Innovation (IMI) led by DOD/AFRL (\$110M BAA anticipated in early Nov)

Electronics – Photonics Integration

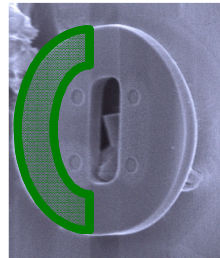
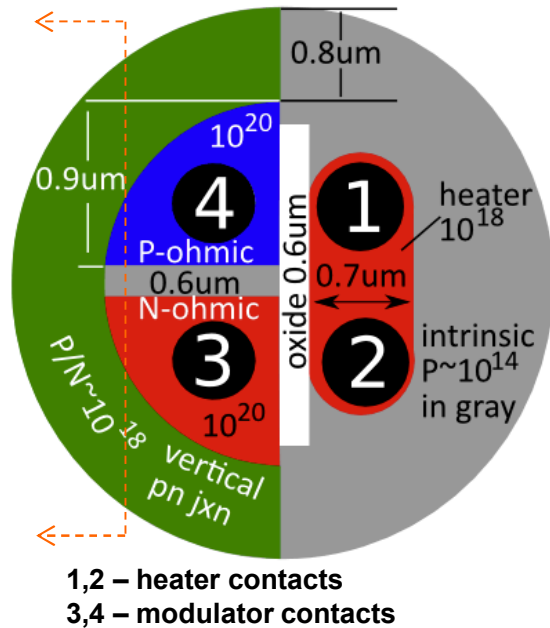
Heterogeneous Integration

- Independent optimization of electronics & photonics
- Challenge: Need high yields and small bond size

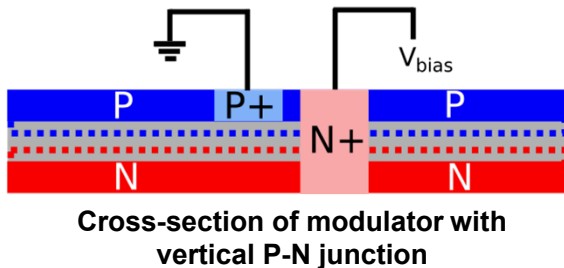
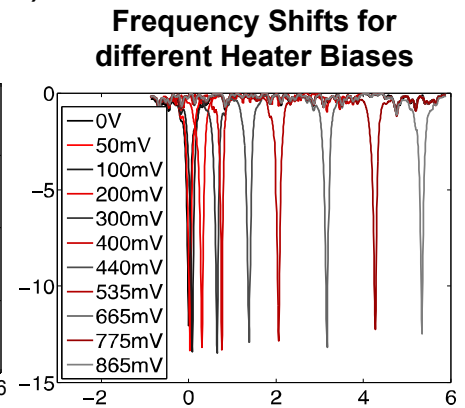
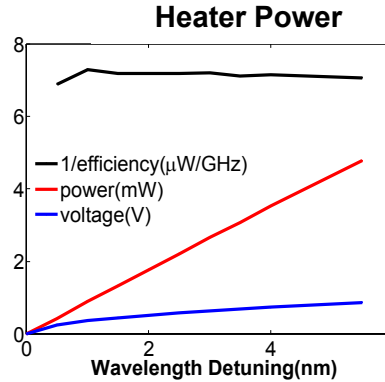
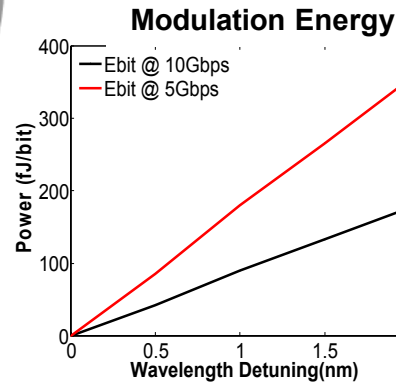


Modulated optical output at 5 Gbps

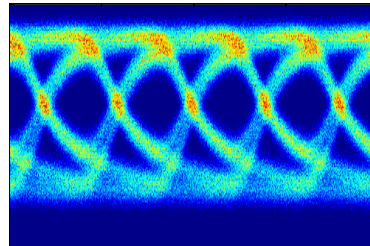
10Gbps Resonant Heater Modulator



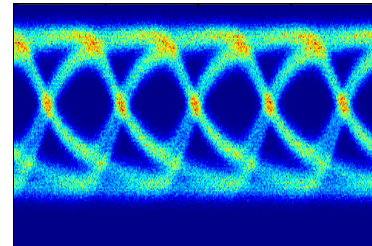
- FSR covers entire C-band
- Low footprint of $\sim 14\mu\text{m}^2$, CMOS-compatible
- Differential signaling compatibility
- Lowest intrinsic tuning energy
 $7\mu\text{W}/\text{GHz}$ ($0.7\text{fJ}/\text{bit-GHz}$)



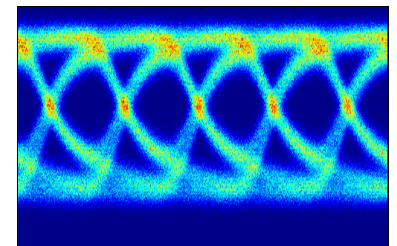
$\Delta\lambda = 0\text{nm}$ $\Delta T = 0\text{C}$ $\phi = 0\text{mV}$ $i = 0\text{A}$



$\Delta\lambda = 2\text{nm}$ $\Delta T = 25\text{C}$ $\phi = 535\text{mV}$ $i = 3.4\text{mA}$



$\Delta\lambda = 5\text{nm}$ $\Delta T = 64\text{C}$ $\phi = 865\text{mV}$ $i = 5.24\text{mA}$

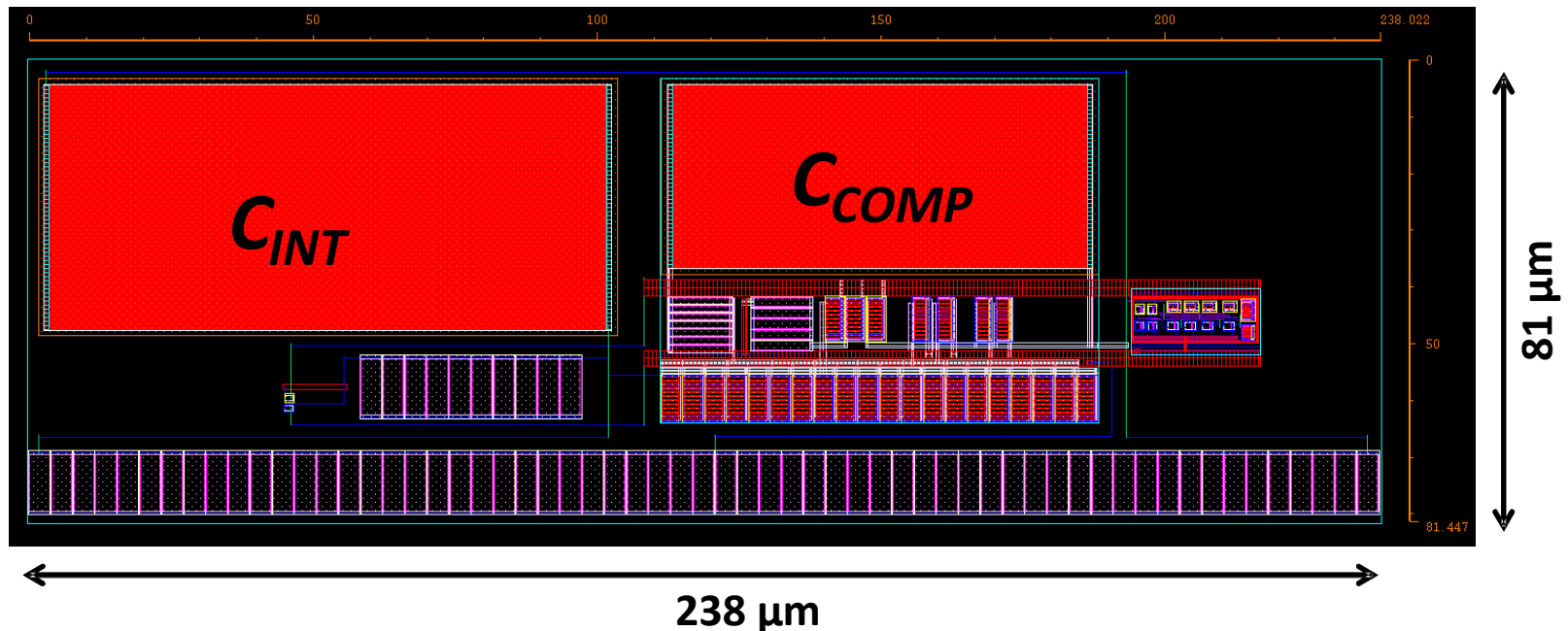


Similar eye diagrams achieved at different tuning temperatures

CMOS ASIC Design (under fab)

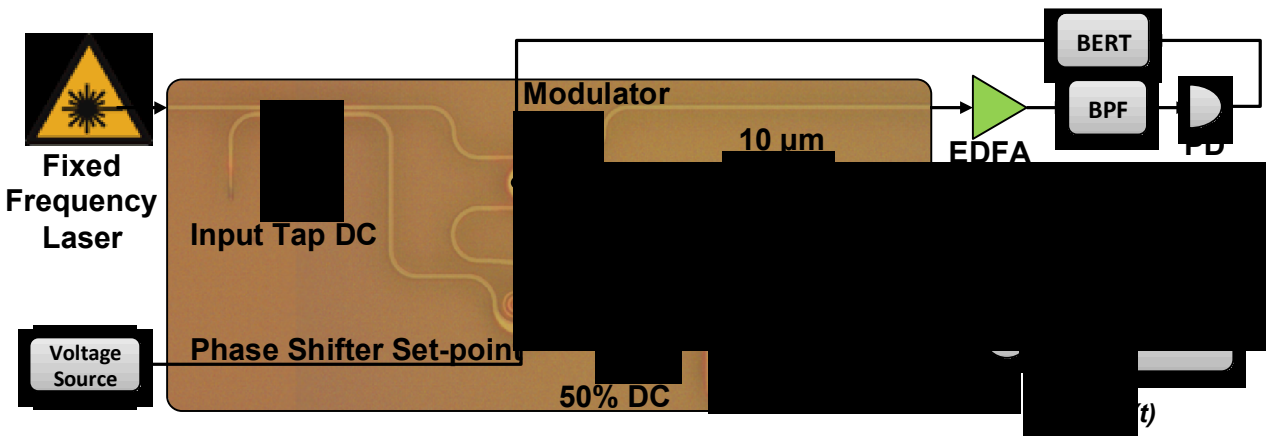
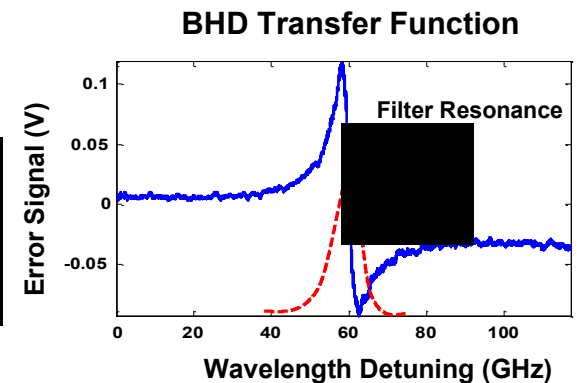
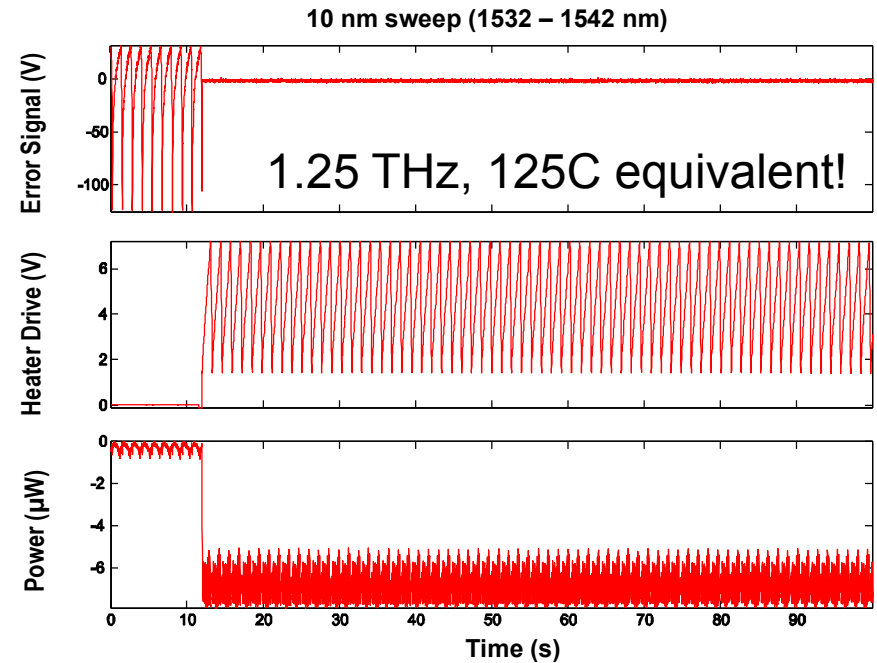
- **IBM 45 nm CMOS ASIC** designed at Sandia
- **Power consumption:** 1.07 mW (steady-state); 0.27 mW (TIA) and 0.8 mW (integrator) (30 – 100 fJ/bit @ 30Gbps-10Gbps) [1]
- **Heater time constant** → large integrator resistor and capacitor in loop filter
- **Heater driver:** Class-B “push-pull”
- **Inverter** implemented with analog switch network

[1] recent result by X. Zheng (OpX 2014)
200 μ W, 2600 μ m² for ‘power meter’ control



Stabilization of Modulators

- **Lock to zero:** No calibration or reference level needed for locking
- **Amplitude insensitive:** Locking point not influenced by optical intensity
- **Precision locking:** Resonator is not disturbed
- **Minimum circuit complexity:** Power and area consumption of control electronics is minimized



Sandia and MPW Fabrication

■ SUMMIT V:

5 layer polysilicon MEMS process

- Developed design manual, DRC, many MPWs over the last decade

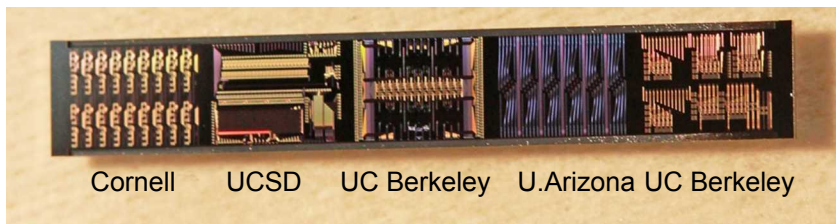
■ CMOS7 Electronics:

Rad-hard, mixed-signal ASIC/ViaArray

- 0.35 μ m, 3.3V core, 3.3V I/O, Cadence, MPWs since 2009

■ SPP1 Silicon Photonics Process:

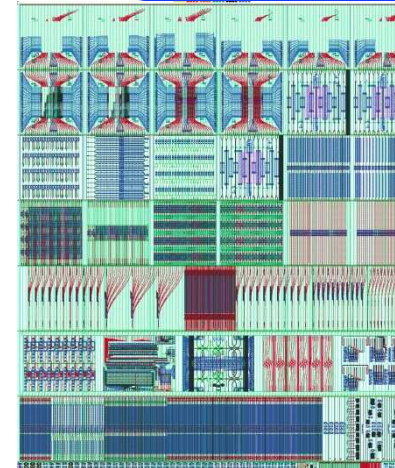
- 250nm Si/3000nm BOx
- fJ/bit mods, 45 GHz dets, filters, etc.
- SiN 2-layer guides/xovers
- Design manual, initial DRC, pilot MPW runs



4. TECHNOLOGY OVERVIEW



SNL has developed a Microsystems and Engineering Sciences Center (MES) located in a limited classified area. Trusted custom fabrication of silicon and silicon technologies for digital, analog and mixed signal ICs is currently available. The MES provides production micro-electronics components to support special DOE and DOD programs. The MES is designed to integrate the numerous scientific disciplines of microelectronics, electrical, mechanical, and chemical engineering. This suite of facilities includes 400,000 square feet and includes cleanroom facilities, laboratories and



The photonic process (SPP1) has been engineered and matured in the MESA process which can be seen in the cross-sections. The process is an integrated circuit (IC) wafer thin SPP1 are two layers one in crystalline silicon and silicon nitride, a full thickness of Germanium with a low resistance ohmic interconnect layer(s), which is all surrounded by a thin layer of silicon nitride. The process technology is a photonic integrated circuit (PIC) process. SPP1 has enabled a wide range of photonic demonstrations, including ultra low energy optical modulators [4], high speed optical modulators [6] and the resonant frequency optical filters [7] and modulators [8].

Figure 4-1 A cartoon illustration of the cross-section of Sandia's SPP1 process with a subset of the possible implant configurations

PROCESS DETAILS

The process flow of are described in Table 5-1. The base process can be broken

